

Nano@Stanford Fellowship

Alison Bick

Advisor: Tom Carver

Process Overview

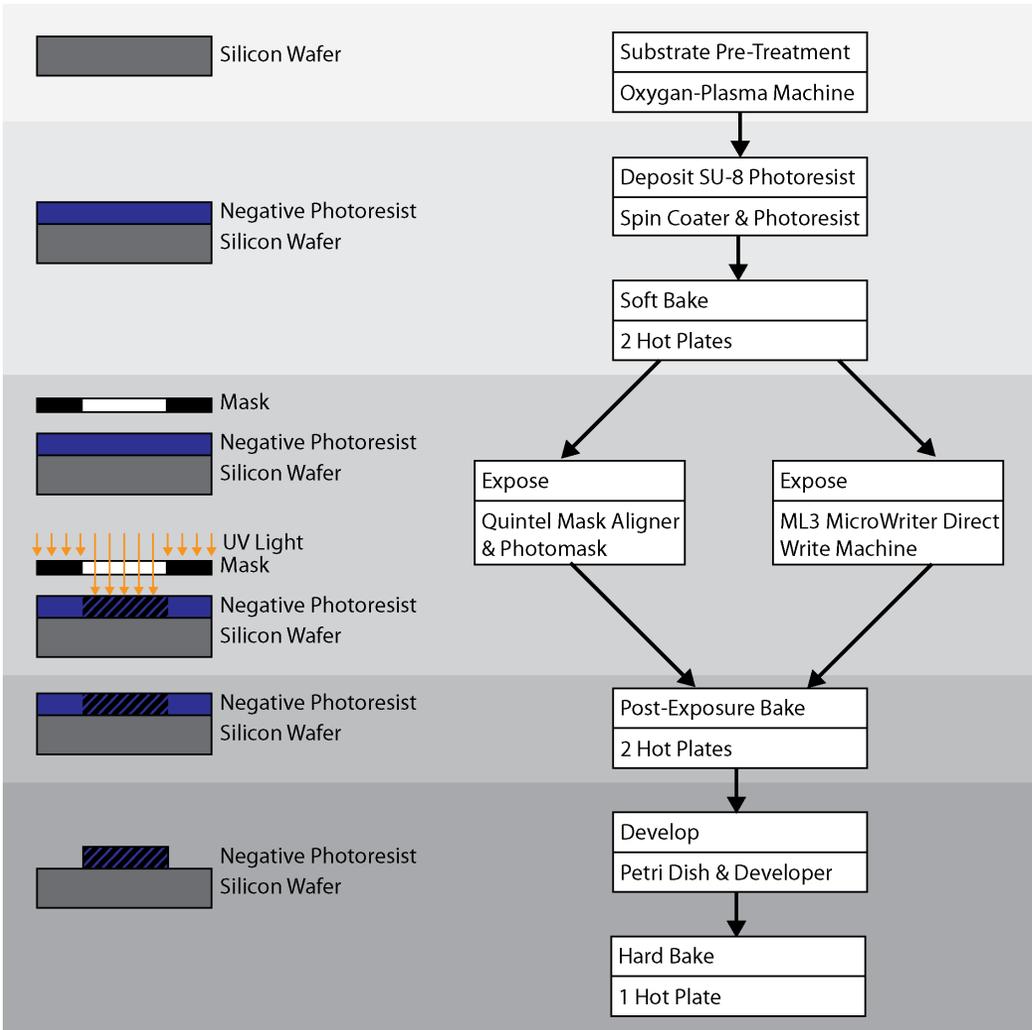
Part 1: Wafer Fabrication

Part 2: Microfluidic Device Manufacturing

Process Overview

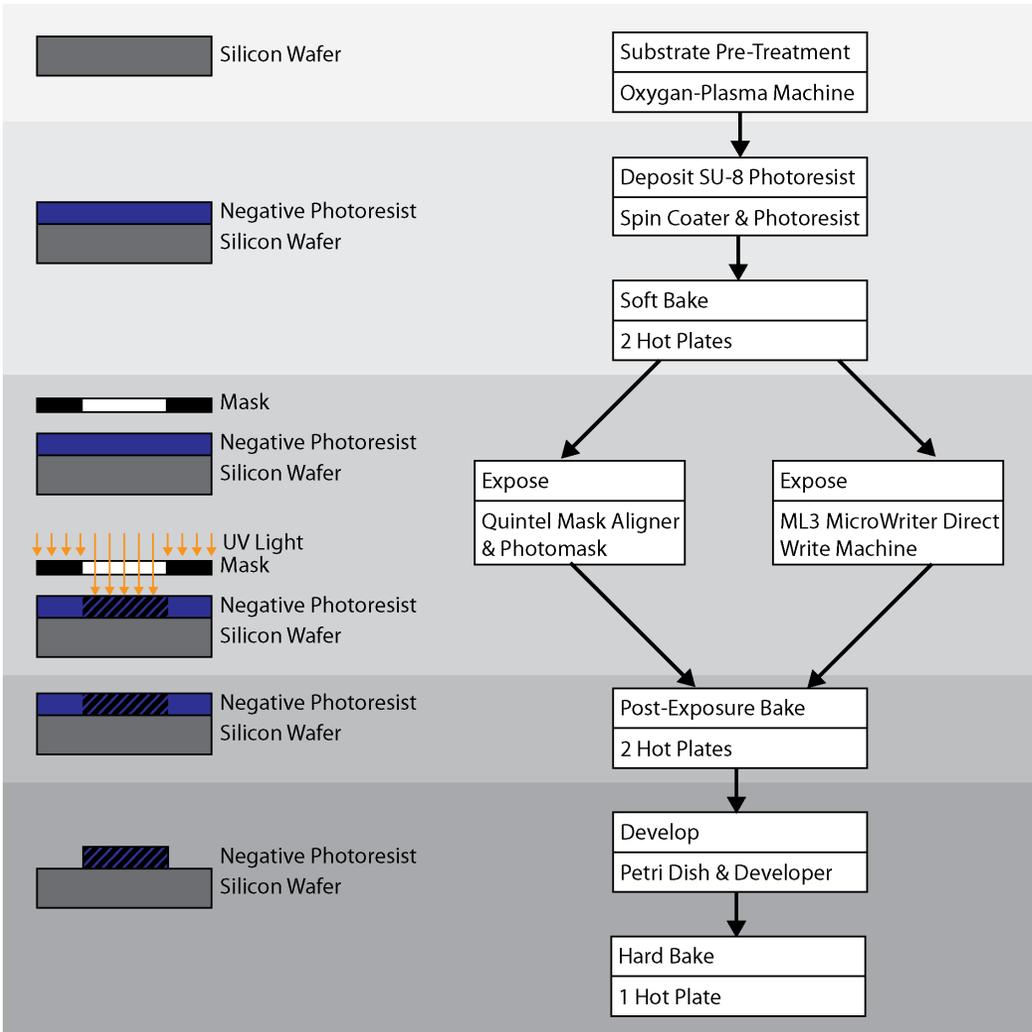
Part 1: Wafer Fabrication

Part 2: Microfluidic Device Manufacturing

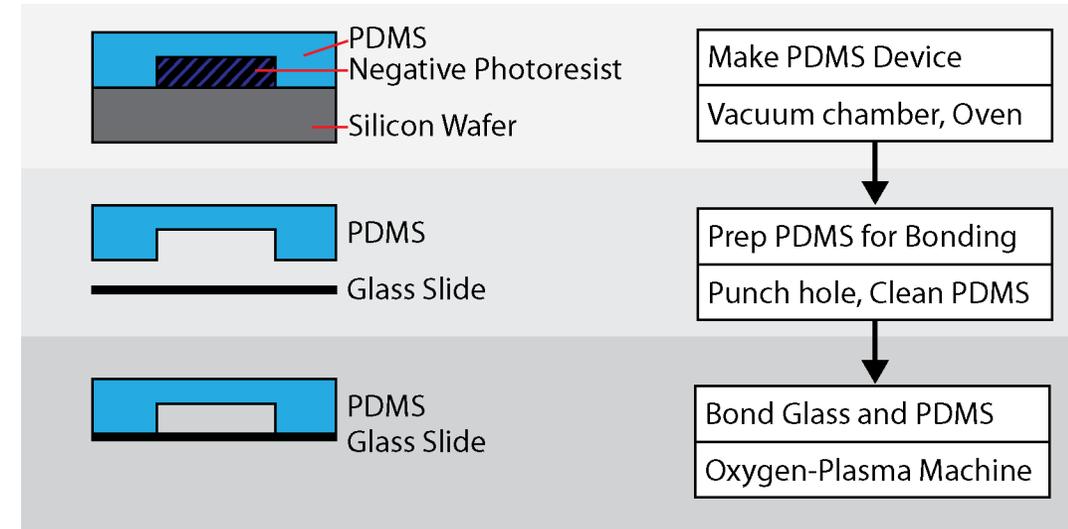


Process Overview

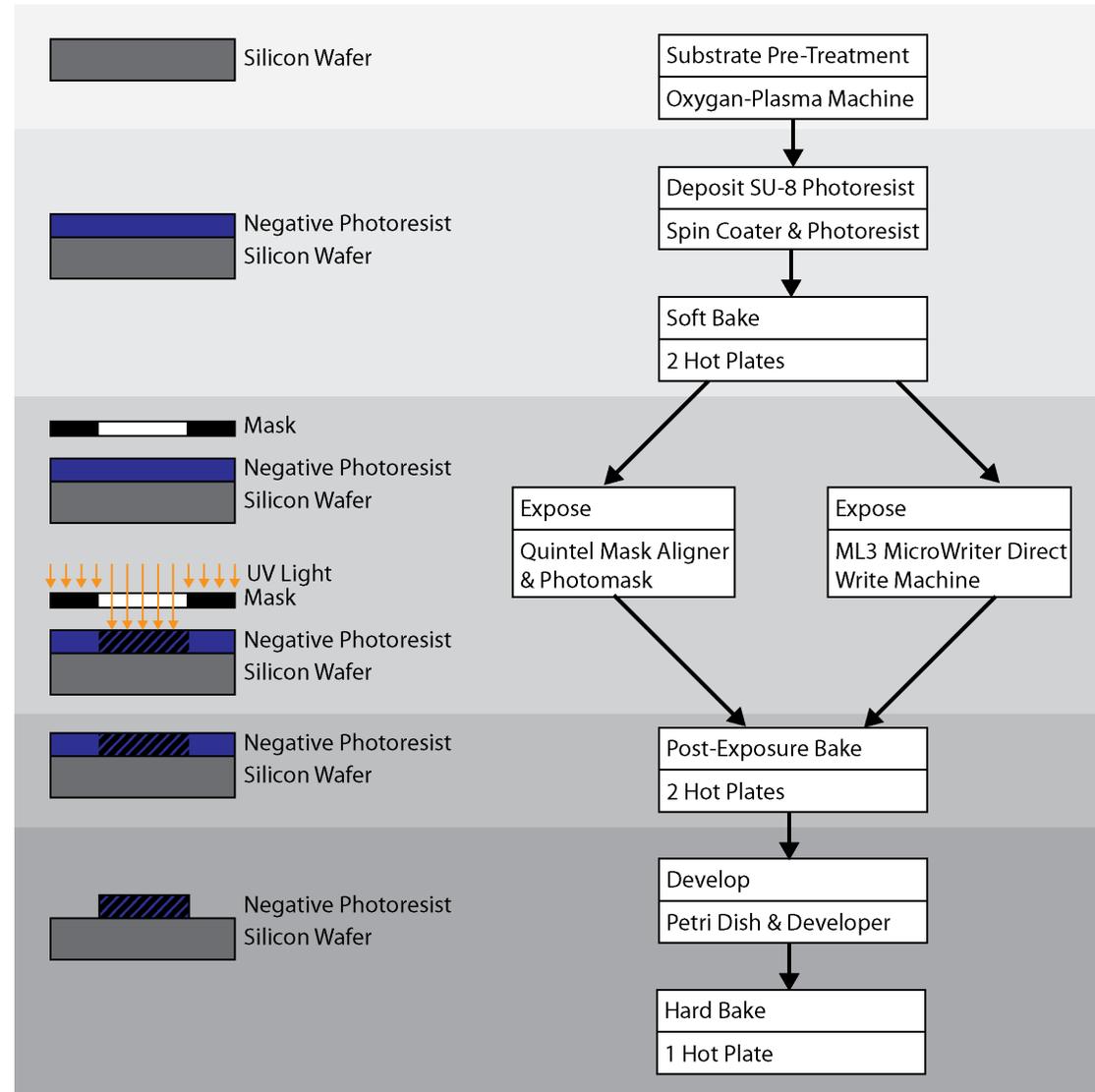
Part 1: Wafer Fabrication



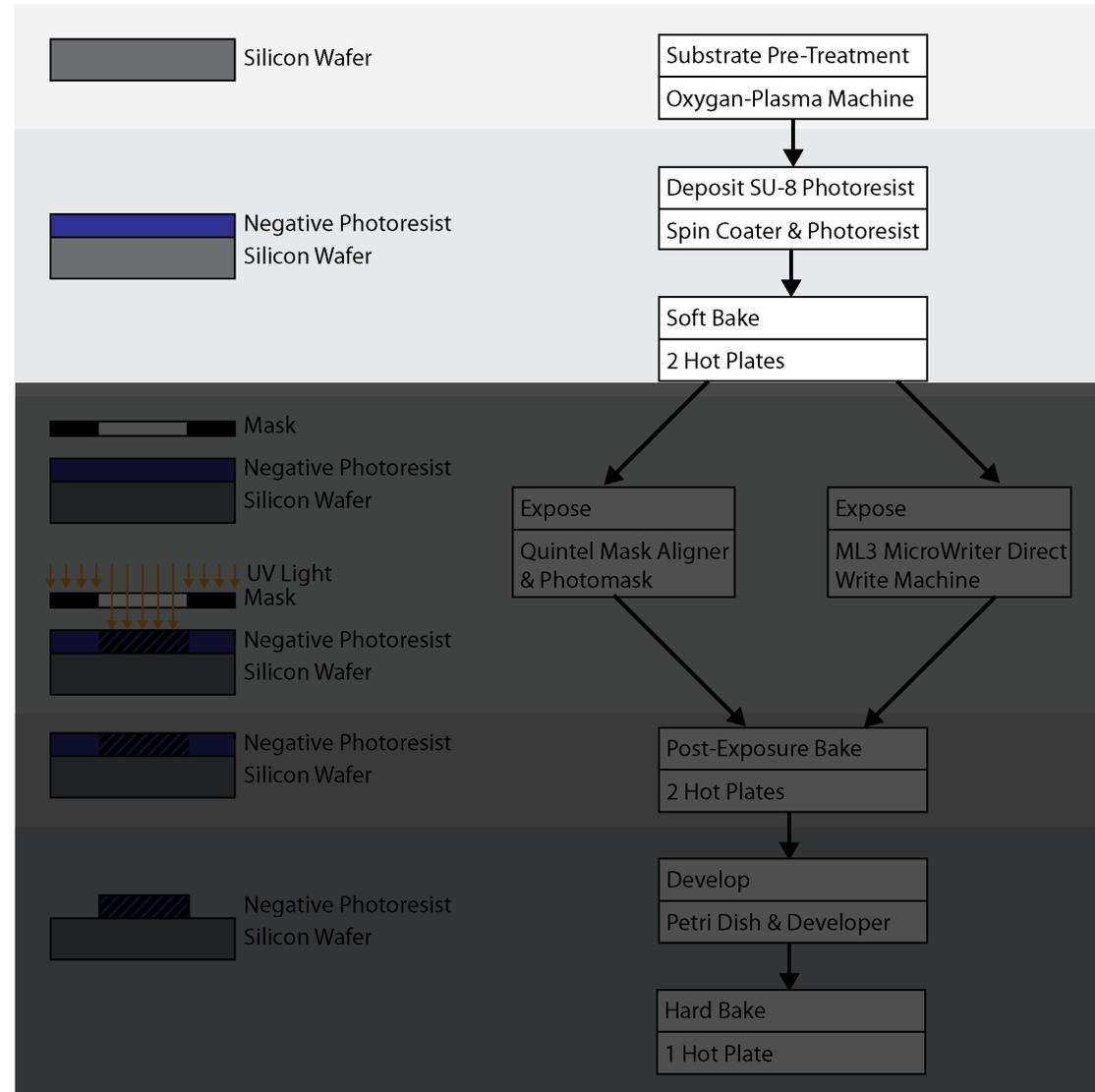
Part 2: Microfluidic Device Manufacturing



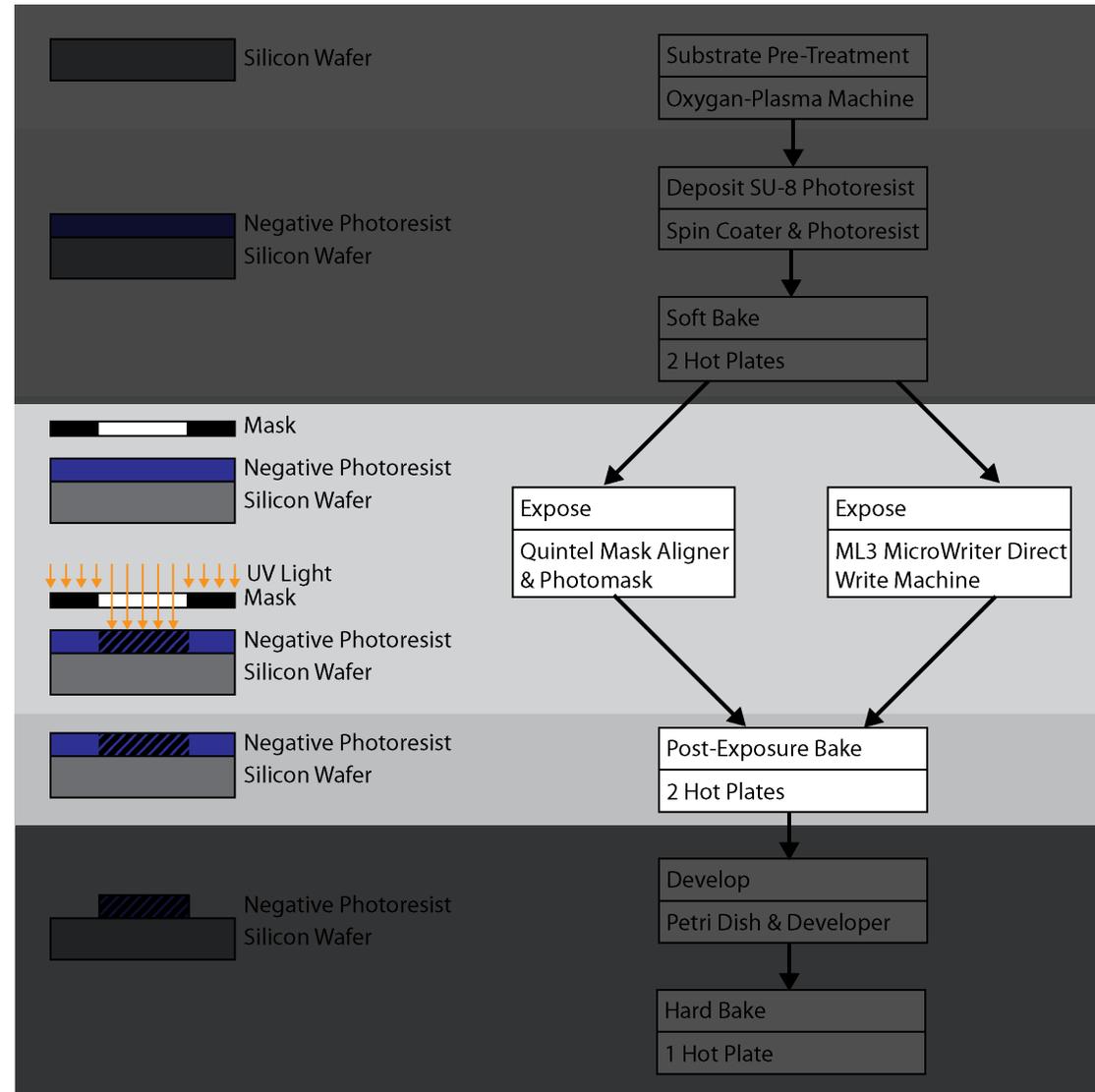
Part 1: Wafer Fabrication



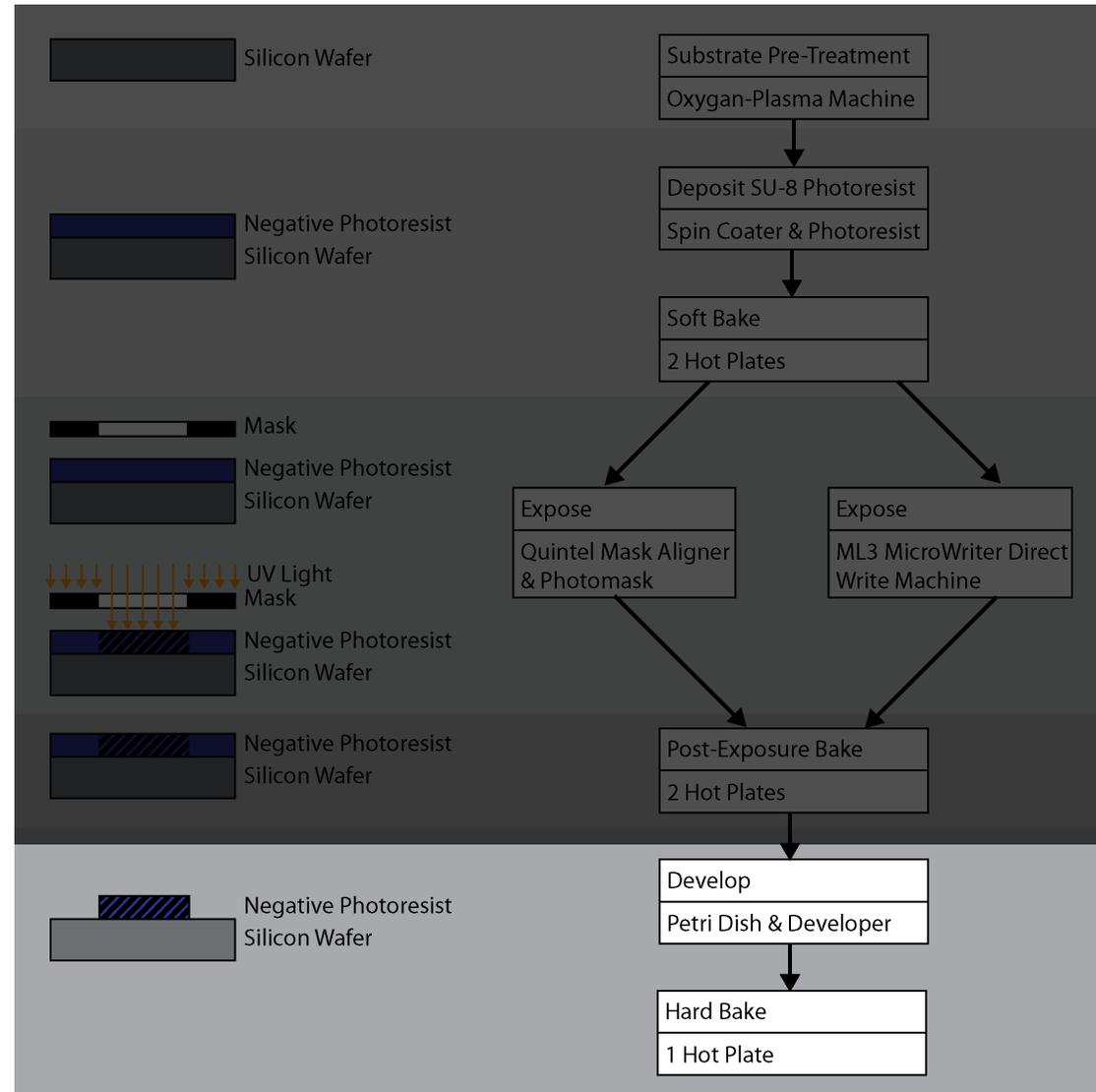
Part 1: Wafer Fabrication



Part 1: Wafer Fabrication



Part 1: Wafer Fabrication



Silicon Wafer

Substrate Pre-Treatment

Oxygen-Plasma Machine

Negative Photoresist
Silicon Wafer

Deposit SU-8 Photoresist

Spin Coater & Photoresist

Mask

Negative Photoresist
Silicon Wafer

Soft Bake

2 Hot Plates

UV Light
Mask

Negative Photoresist
Silicon Wafer

Expose

Quintel Mask Aligner
& Photomask

Expose

ML3 MicroWriter Direct
Write Machine

Negative Photoresist
Silicon Wafer

Post-Exposure Bake

2 Hot Plates

Negative Photoresist
Silicon Wafer

Develop

Petri Dish & Developer

Hard Bake

1 Hot Plate



Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Negative Photoresist
Silicon Wafer

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

Mask
Negative Photoresist
Silicon Wafer

UV Light
Mask
Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Expose
Quintel Mask Aligner
& Photomask

Expose
ML3 MicroWriter Direct
Write Machine

Post-Exposure Bake
2 Hot Plates

Develop
Petri Dish & Developer

Hard Bake
1 Hot Plate

Oxygen-Plasma Cleaner

Stop
Start

Off
On



Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

Expose
Quintel Mask Aligner
& Photomask

Expose
ML3 MicroWriter Direct
Write Machine

Post-Exposure Bake
2 Hot Plates

Develop
Petri Dish & Developer

Hard Bake
1 Hot Plate

Negative Photoresist
Silicon Wafer

Mask
Negative Photoresist
Silicon Wafer

UV Light
Mask
Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

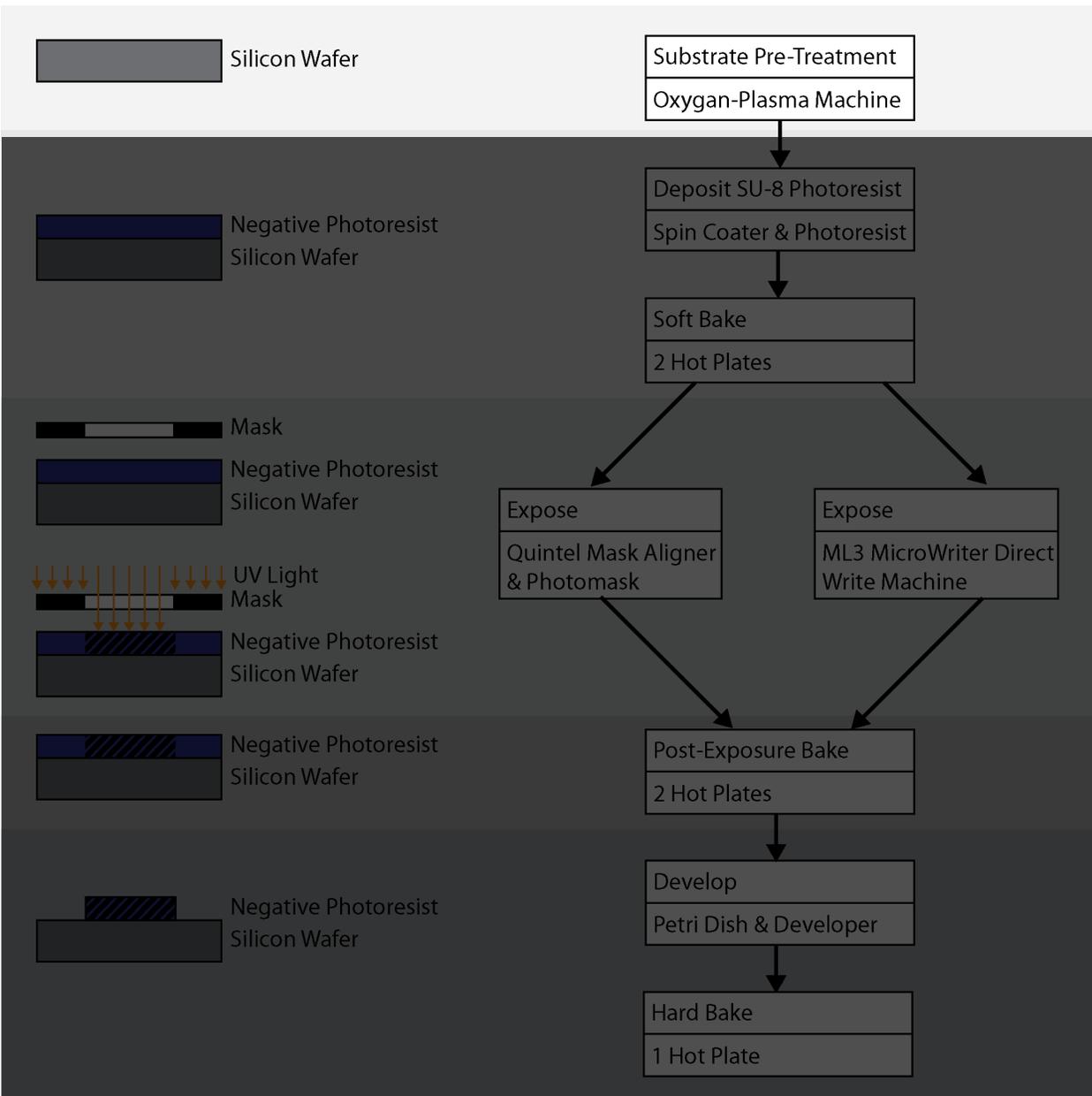
Negative Photoresist
Silicon Wafer

Oxygen-Plasma Cleaner

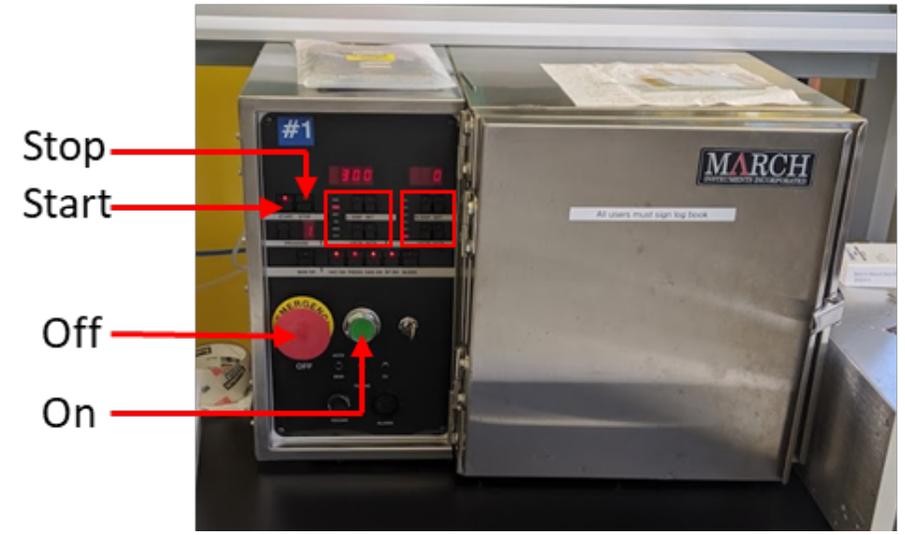


Stop
Start

Off
On



Oxygen-Plasma Cleaner



2. The desired values to treat a silicon wafer are listed below:

Parameter	PRESS	POWER	ENDPT	TIME		
DCBIAS	BP/RP					
Value	80	300	0	600	0	85

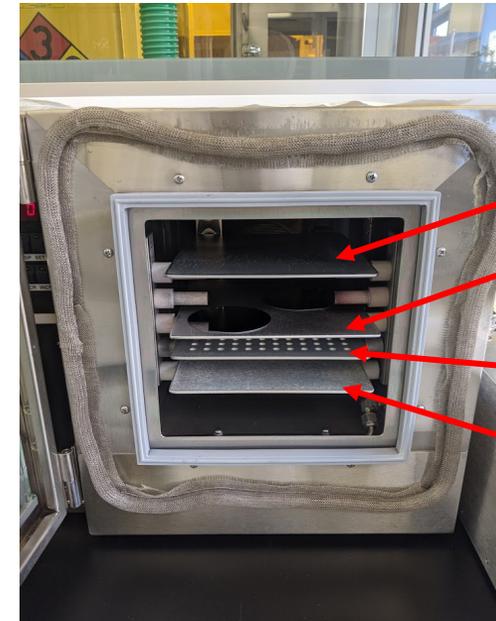
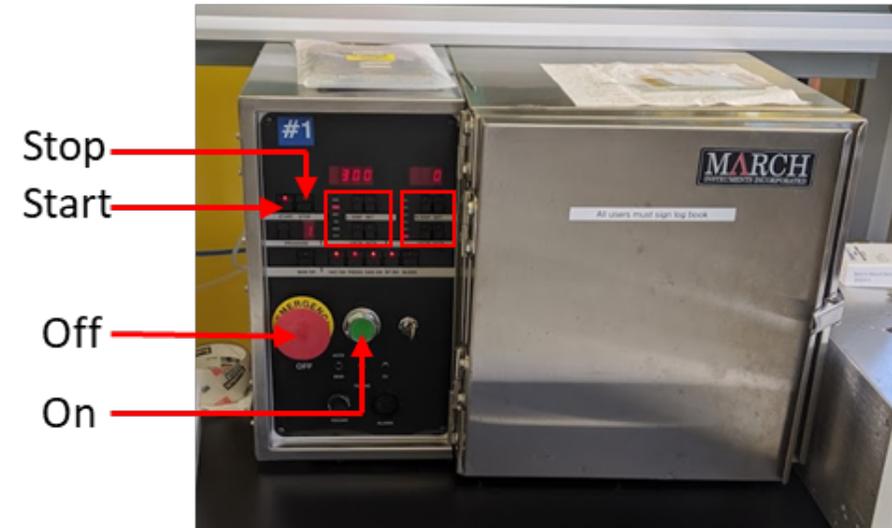
3. The desired values to treat a silicon wafer are listed below:

Parameter	GAS1	GAS2	GAS3	GAS4		
	GAS5	GAS6				
Value	0	2	0	0	0	0

Note: GAS2 is oxygen, you should make sure that GAS1 (nitrogen) is turned off (0).



Oxygen-Plasma Cleaner



- Grounded plate
- Direct plate
- Grounded grid plate
- Indirect (floating) plate

Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Negative Photoresist
Silicon Wafer

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

Mask
Negative Photoresist
Silicon Wafer

UV Light
Mask
Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Expose
Quintel Mask Aligner
& Photomask

Expose
ML3 MicroWriter Direct
Write Machine

Post-Exposure Bake
2 Hot Plates

Develop
Petri Dish & Developer

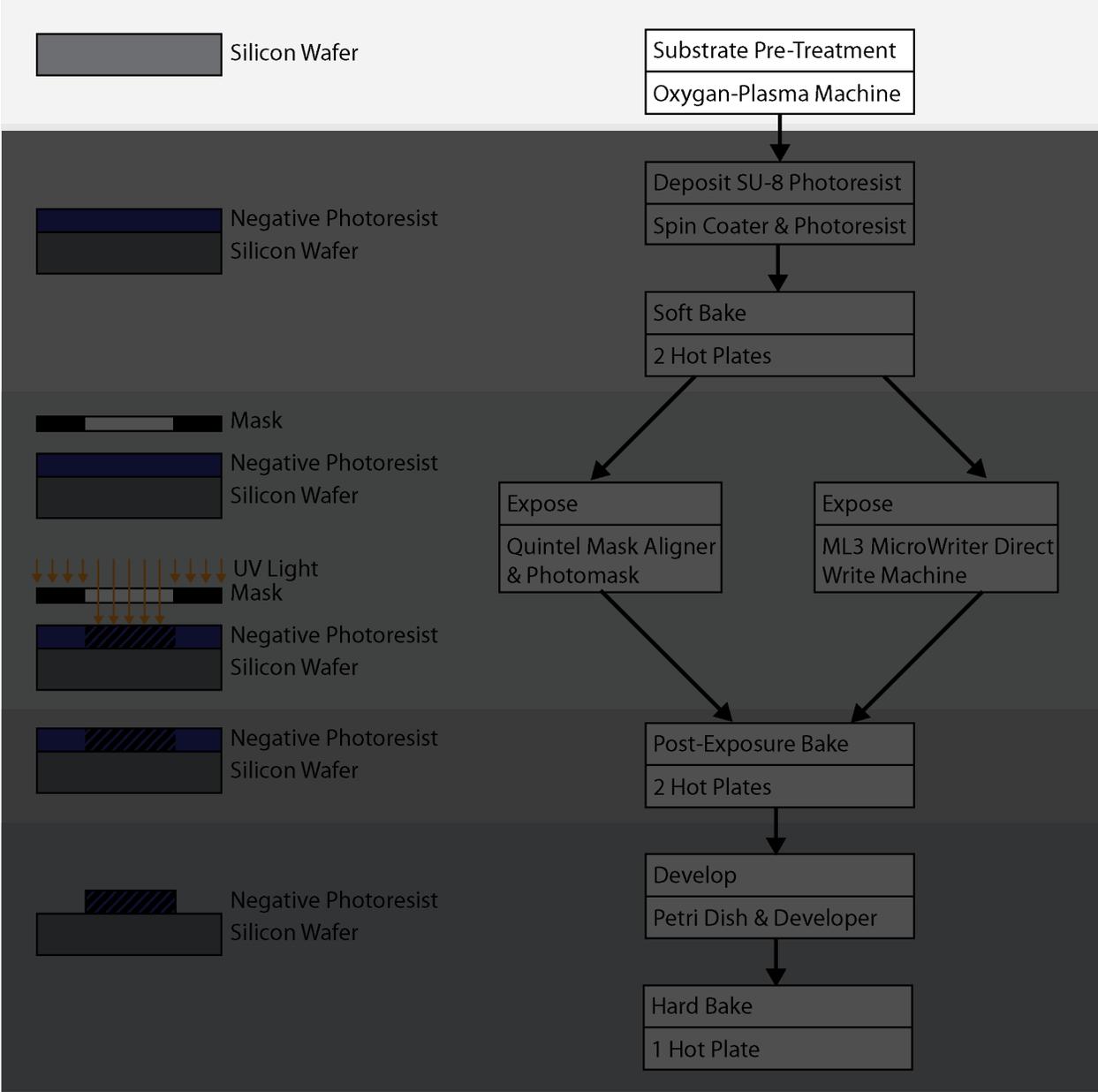
Hard Bake
1 Hot Plate

Oxygen-Plasma Cleaner

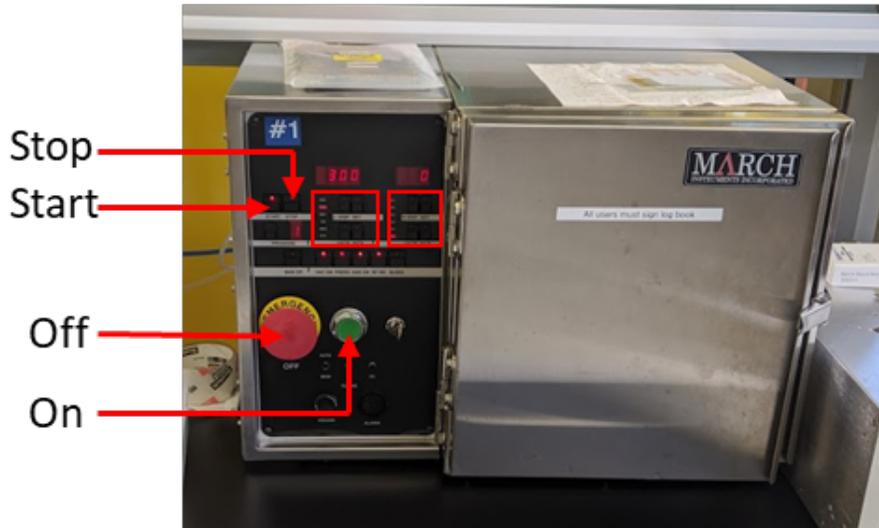
Stop
Start

Off
On





Oxygen-Plasma Cleaner



Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Negative Photoresist
Silicon Wafer

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

Mask
Negative Photoresist
Silicon Wafer

UV Light
Mask
Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Expose
Quintel Mask Aligner
& Photomask

Expose
ML3 MicroWriter Direct
Write Machine

Post-Exposure Bake
2 Hot Plates

Develop
Petri Dish & Developer

Hard Bake
1 Hot Plate

Oxygen-Plasma Cleaner

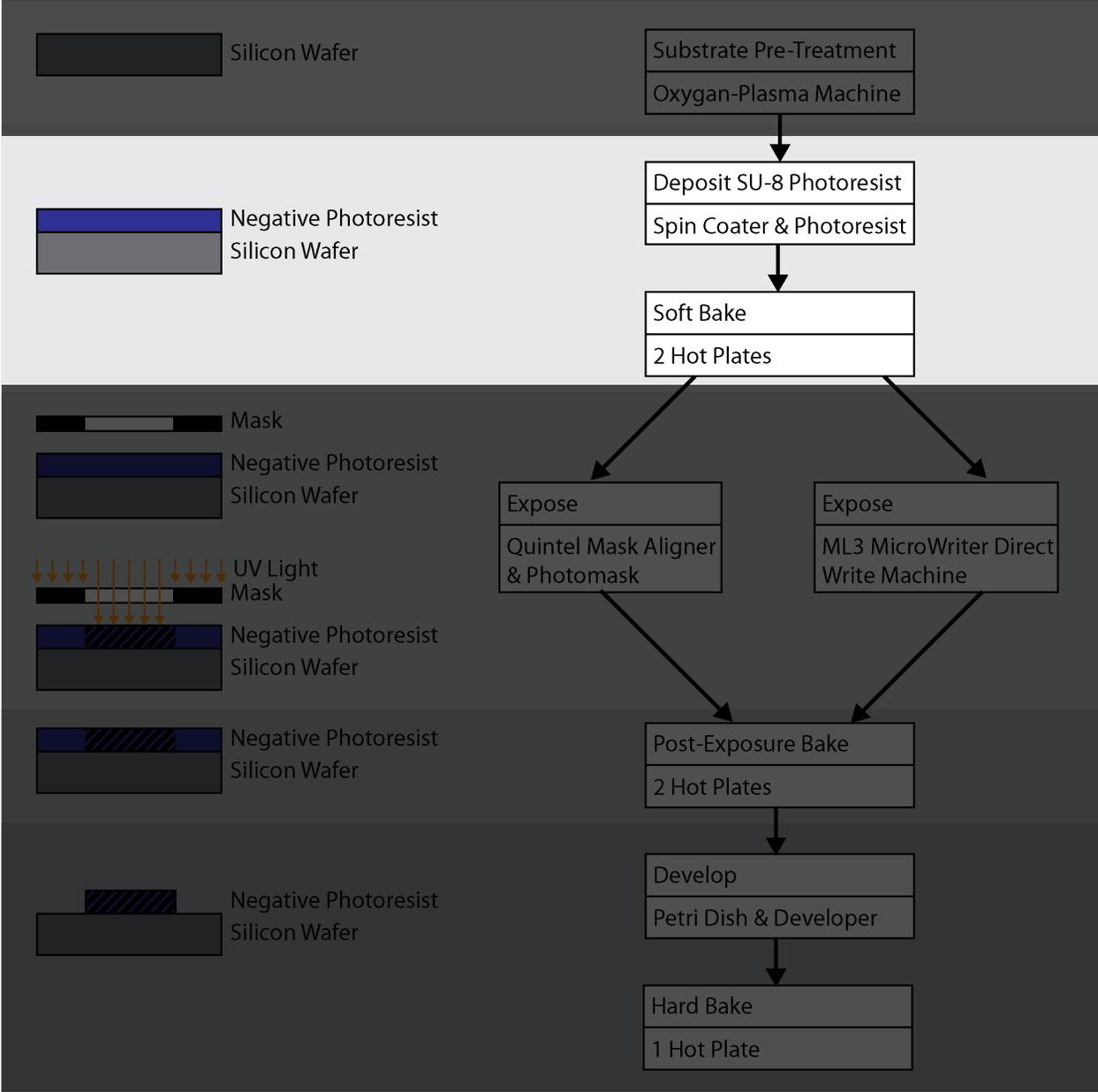
Stop

Start

Off

On





Substrate Pre-Treatment
Oxygen-Plasma Machine

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

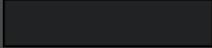
Expose
Quintel Mask Aligner & Photomask

Expose
ML3 MicroWriter Direct Write Machine

Post-Exposure Bake
2 Hot Plates

Develop
Petri Dish & Developer

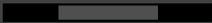
Hard Bake
1 Hot Plate



Silicon Wafer



Negative Photoresist
Silicon Wafer



Mask



Negative Photoresist
Silicon Wafer



UV Light Mask



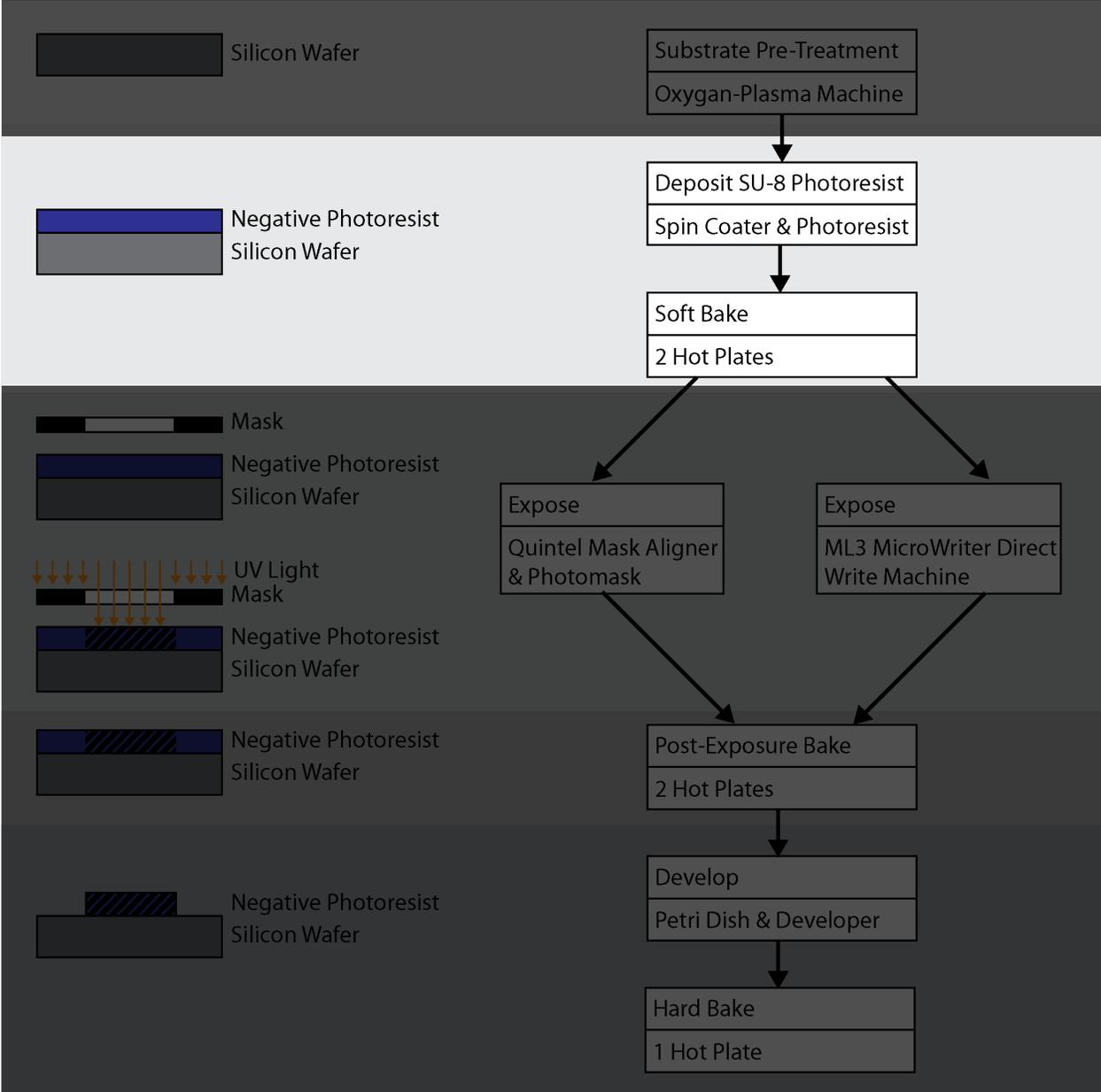
Negative Photoresist
Silicon Wafer



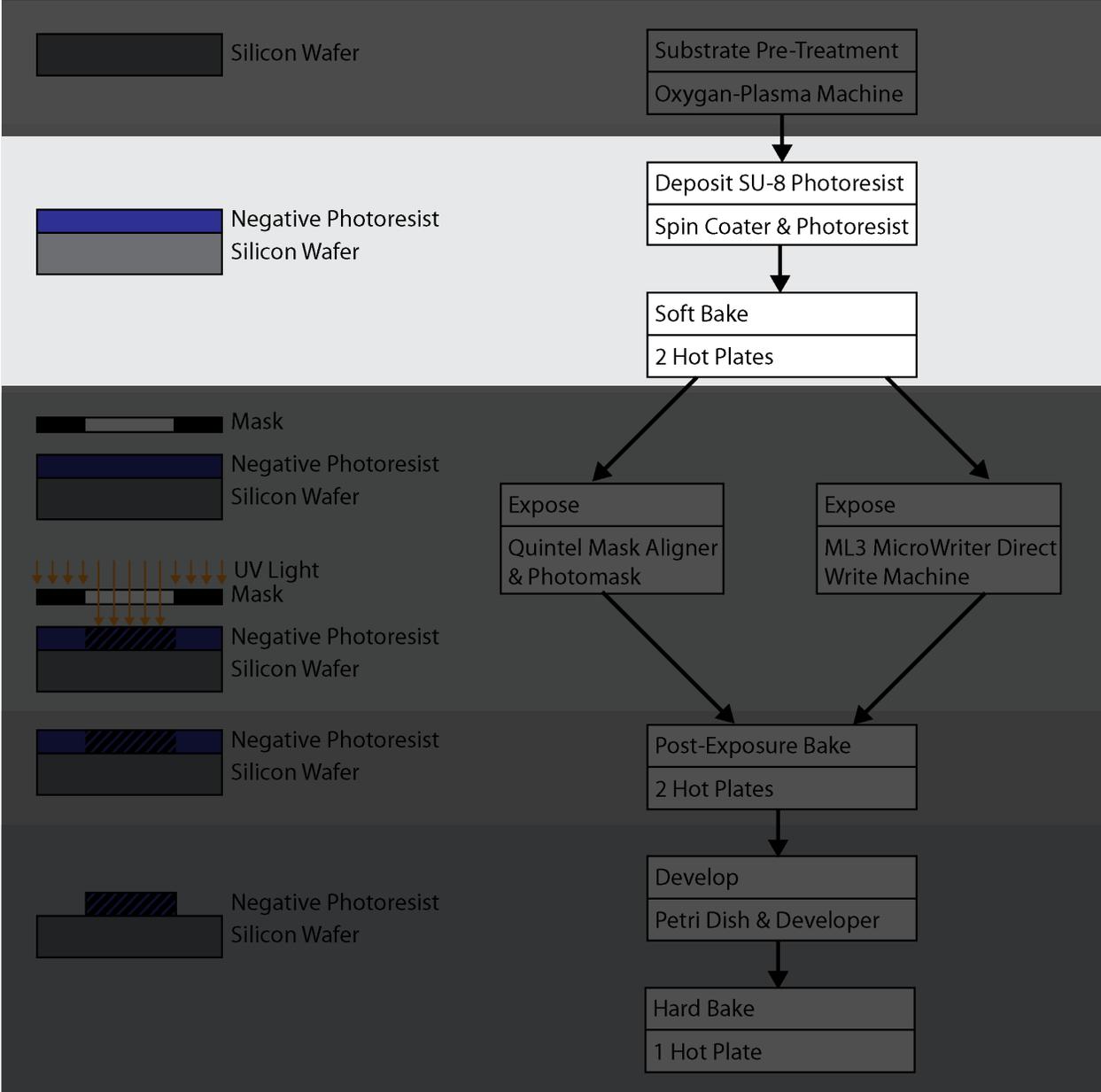
Negative Photoresist
Silicon Wafer



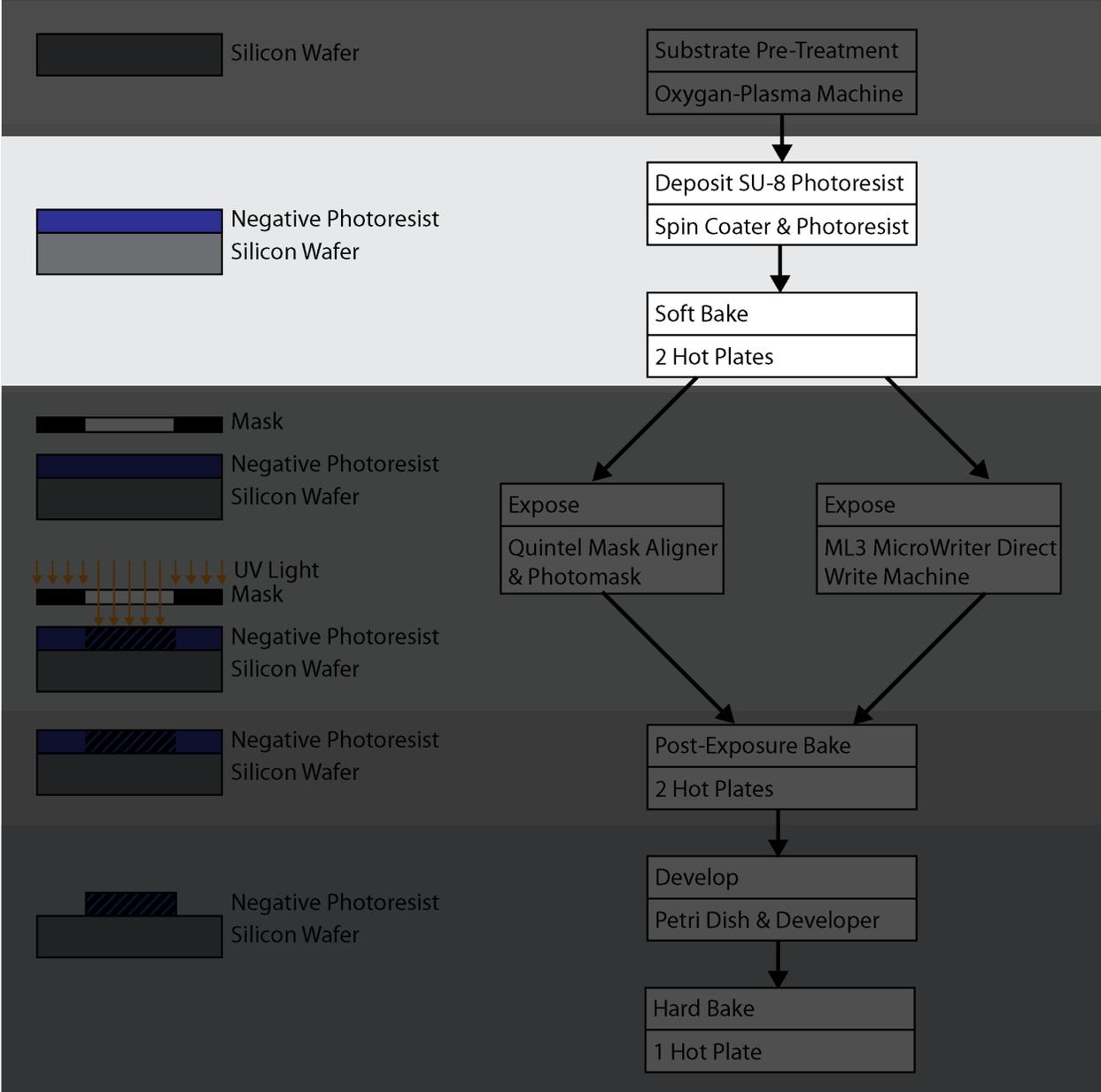
Negative Photoresist
Silicon Wafer



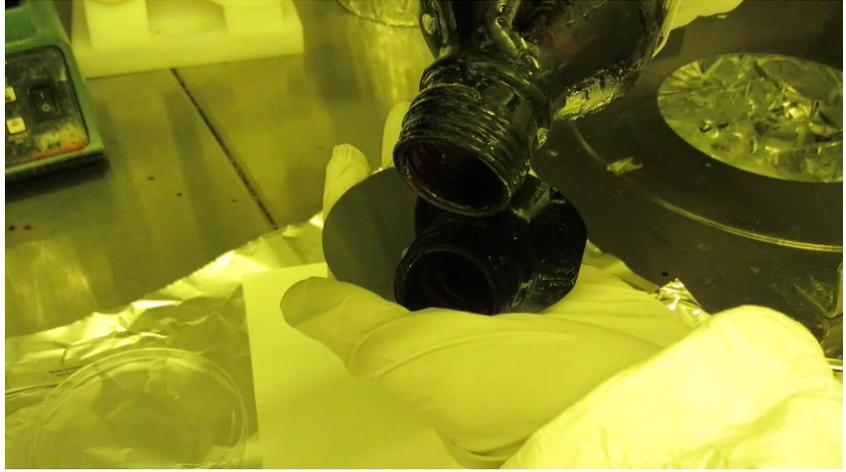
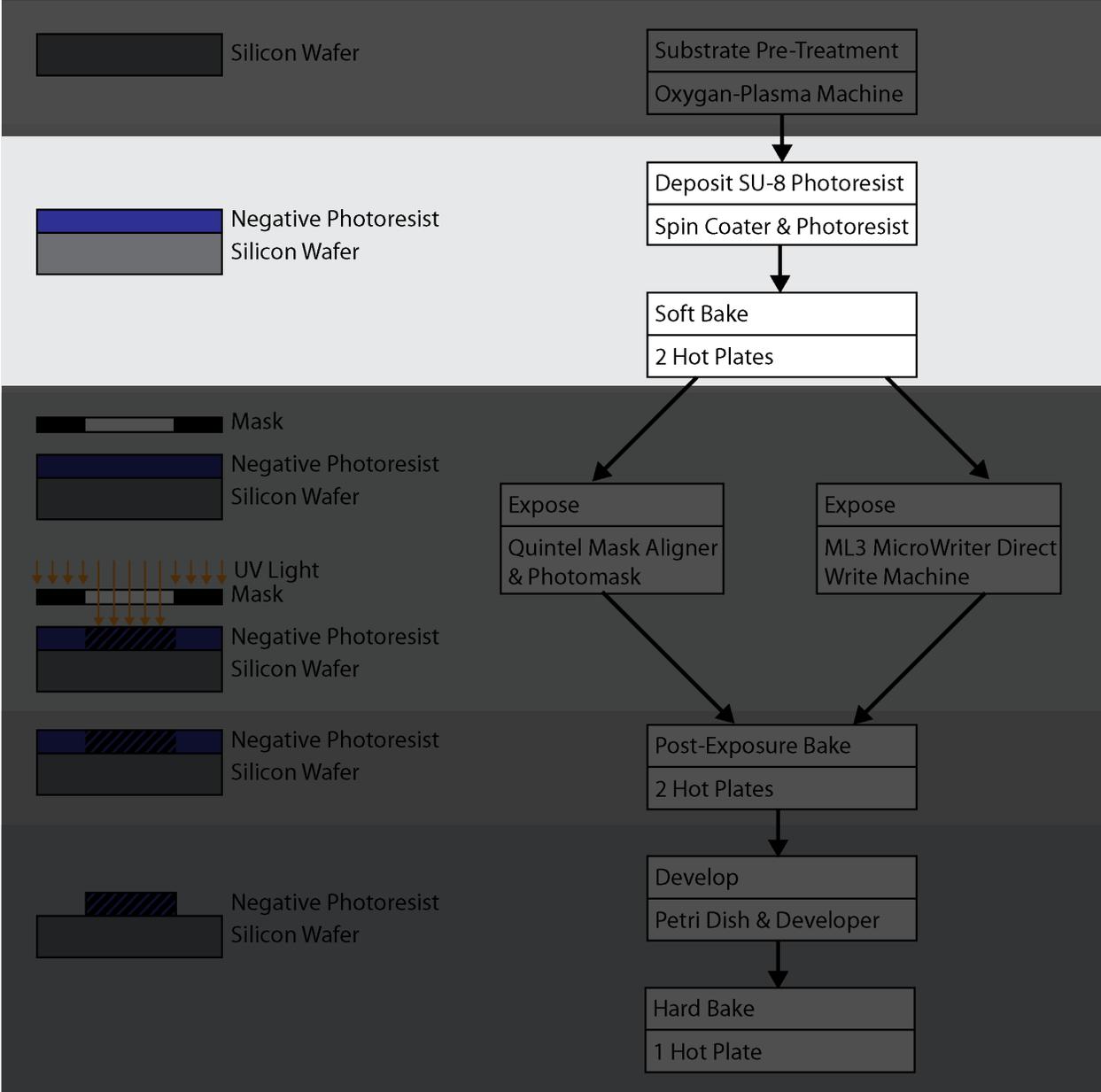
Wafer
Foil
Spin coater base

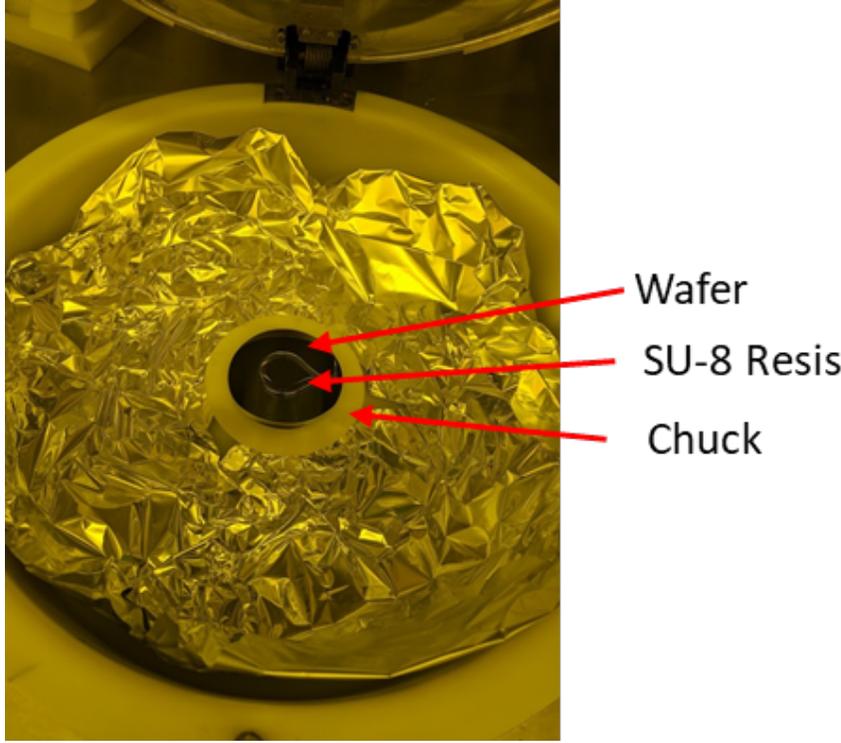
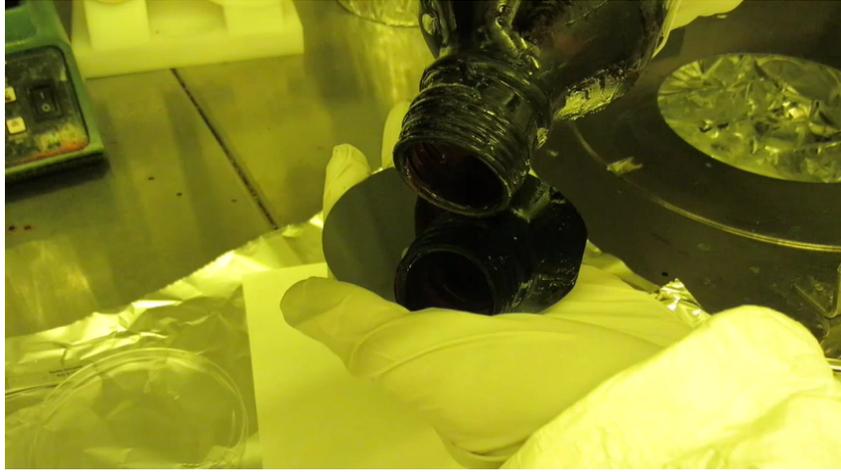
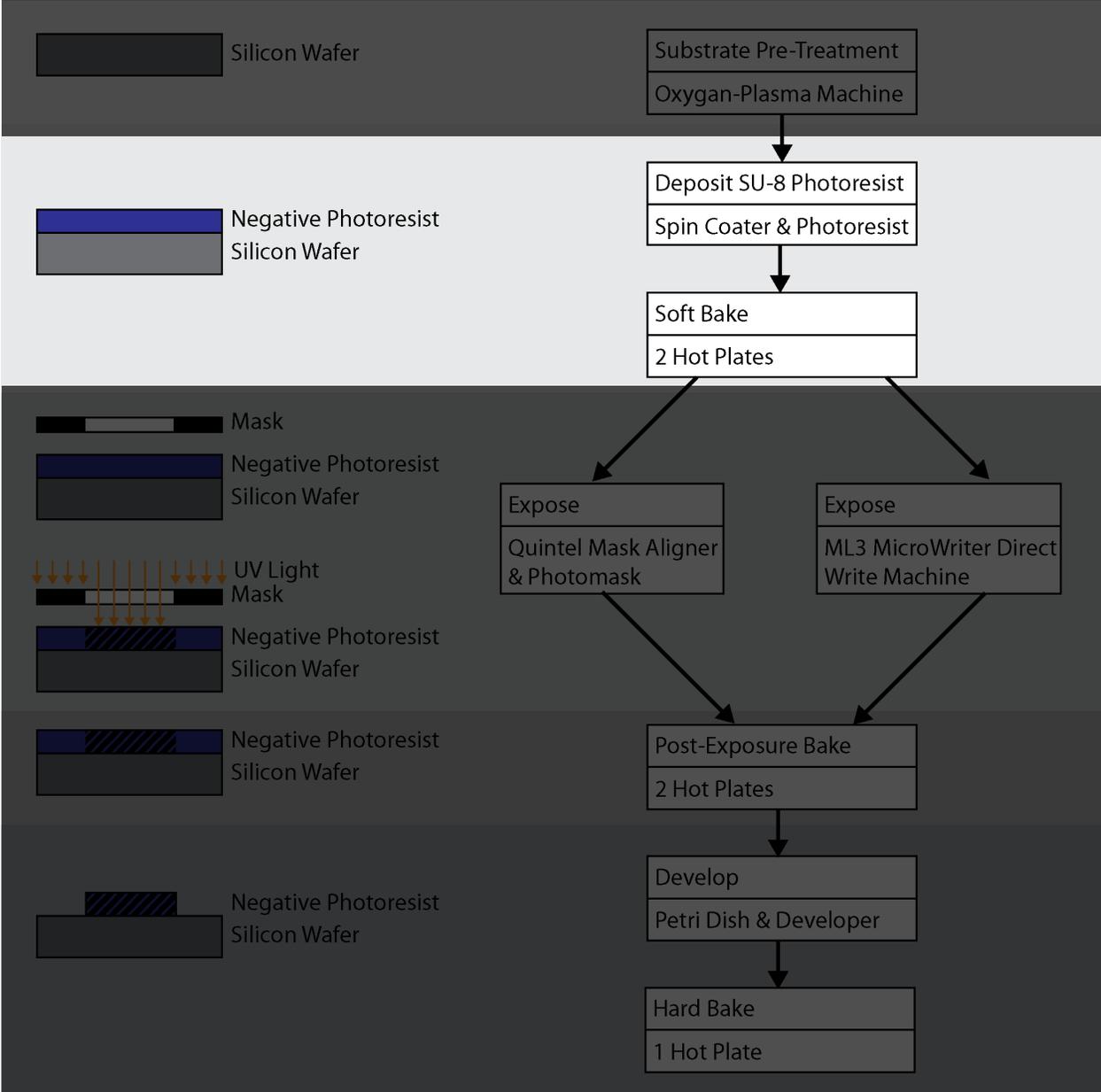


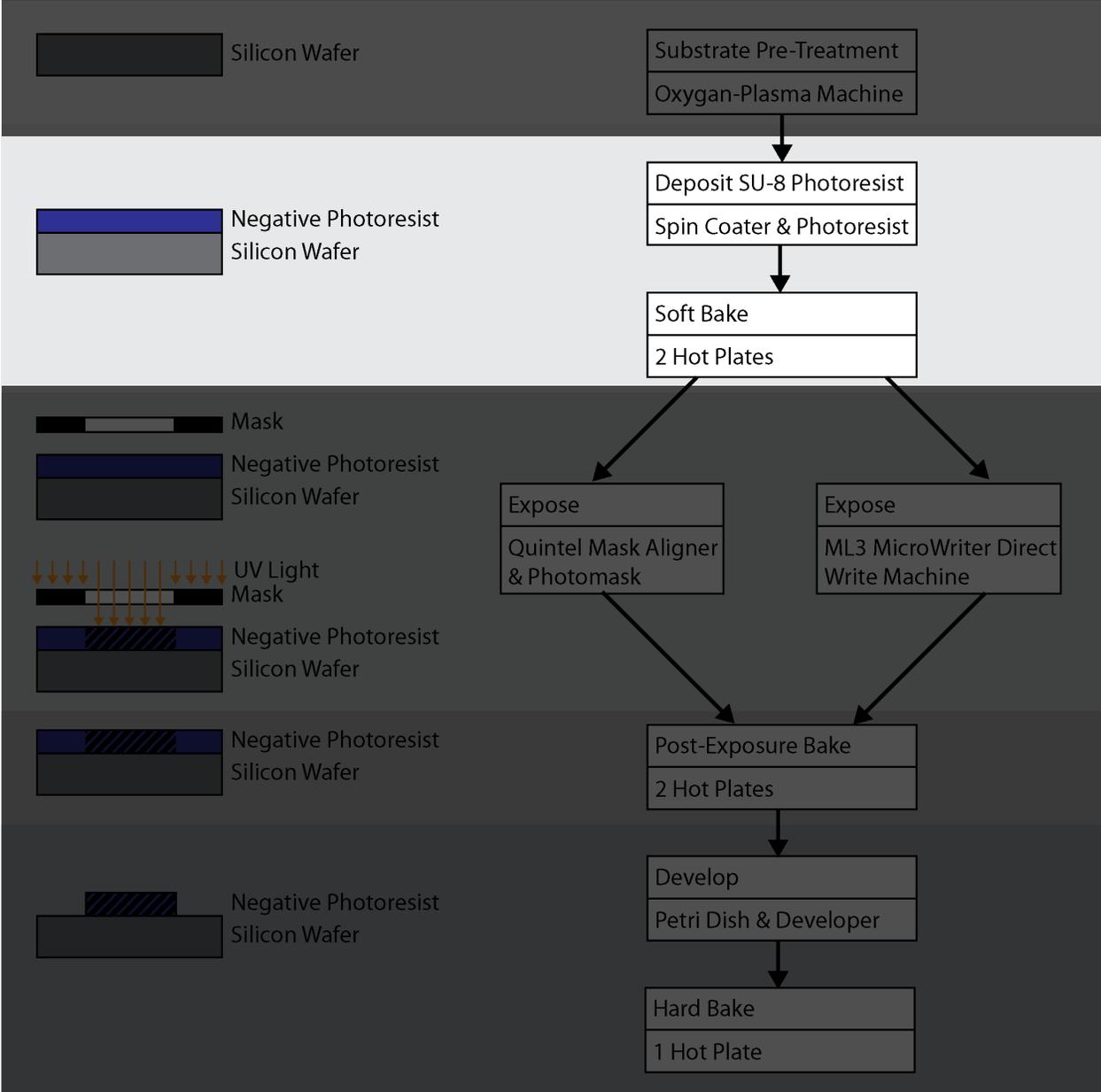
Wafer
Foil
Spin coater base



Wafer
Foil
Spin coater base







Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Negative Photoresist
Silicon Wafer

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

Mask

Negative Photoresist
Silicon Wafer

UV Light
Mask

Negative Photoresist
Silicon Wafer

Expose
Quintel Mask Aligner
& Photomask

Expose
ML3 MicroWriter Direct
Write Machine

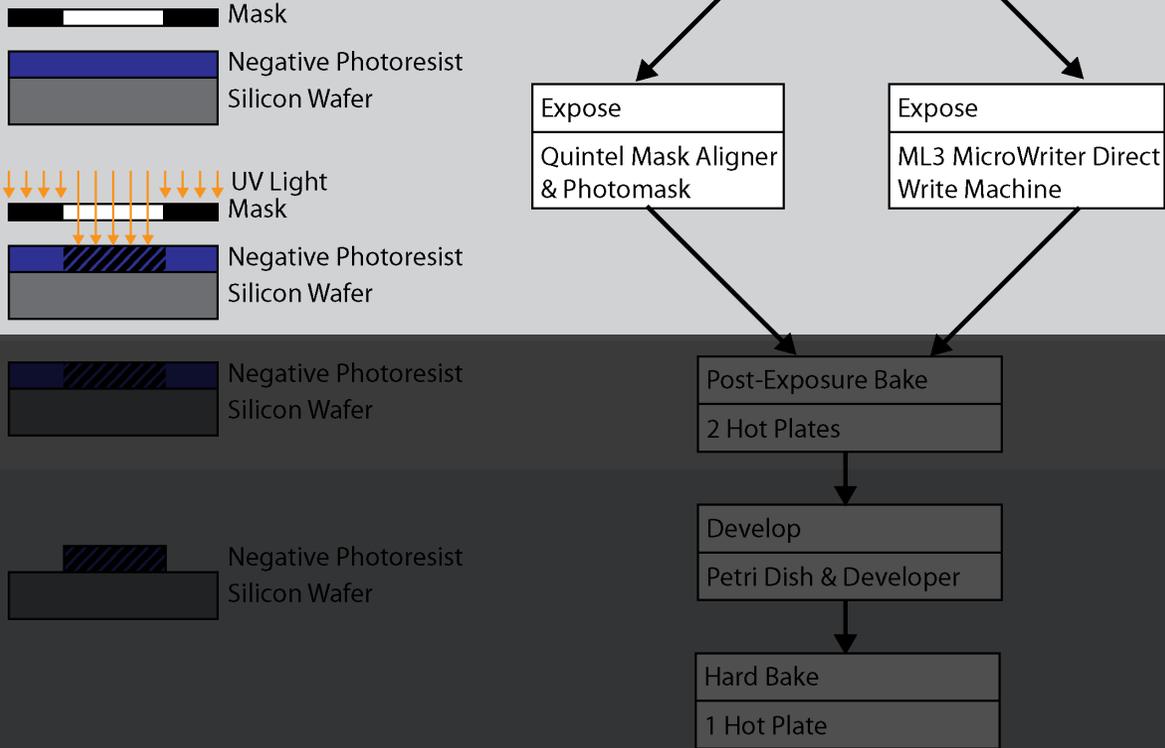
Negative Photoresist
Silicon Wafer

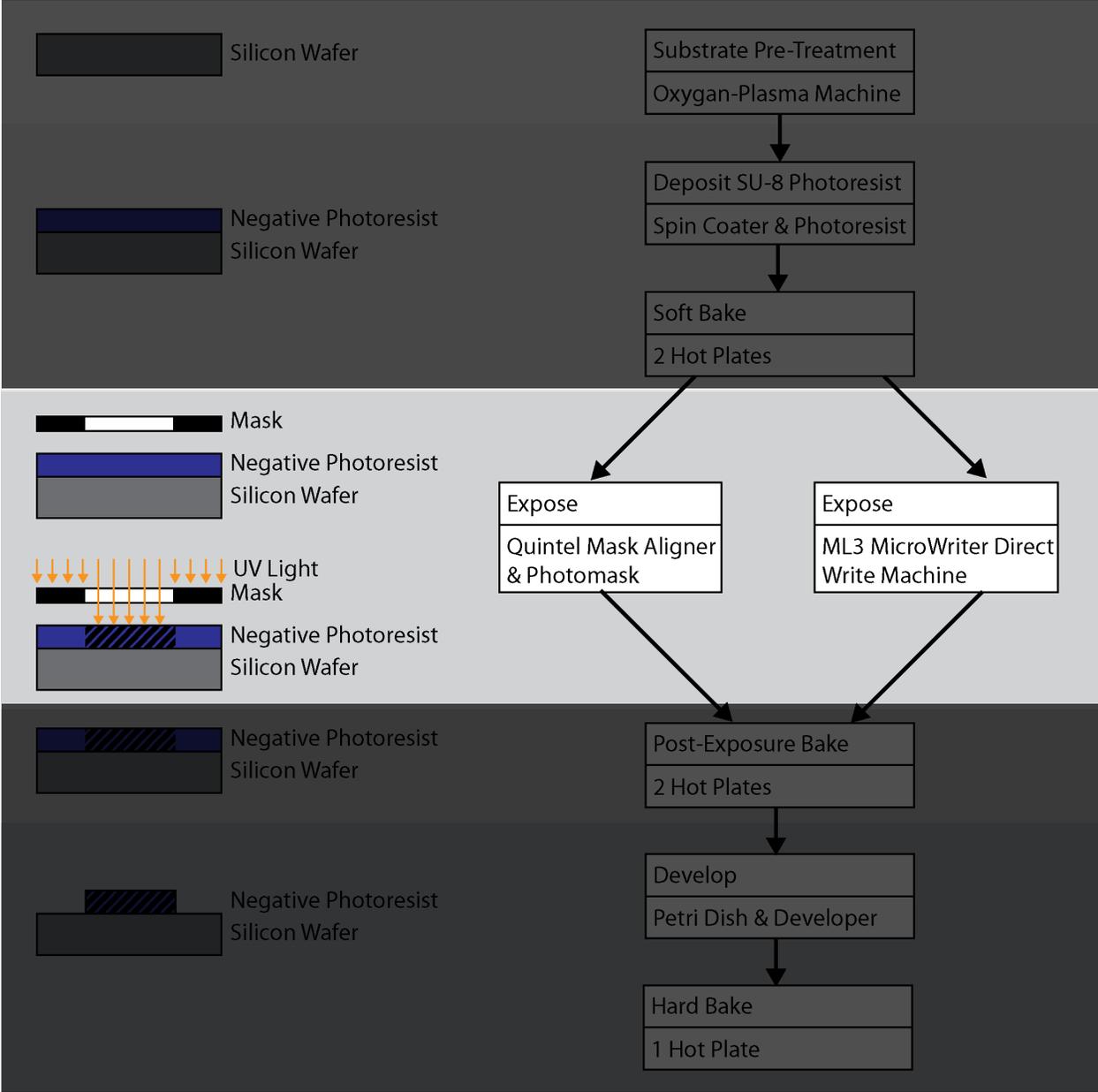
Post-Exposure Bake
2 Hot Plates

Negative Photoresist
Silicon Wafer

Develop
Petri Dish & Developer

Hard Bake
1 Hot Plate





	Quintel	ML3
Pros	<ul style="list-style-type: none"> Fast exposure time Quick repetitions of one device design 	<ul style="list-style-type: none"> Can design digital mask and write with it in the same day Do not need to order shadow mask
Cons	<ul style="list-style-type: none"> Need to make shadow mask (Tang Lab orders masks from CAD/ART services, https://www.outputcity.com/) 	<ul style="list-style-type: none"> Very slow to write due to 385nm UV source. Ghost lines at stitch locations due to optical interference at interfaces of write-fields. Channel designs must be converted to .cif format using Clewin software
Other notes	<ul style="list-style-type: none"> Tang lab uses Quintel to make most devices due to less time and money to make a full wafer of designs 	<ul style="list-style-type: none"> Tang lab uses ML3 to prototype a single device design.











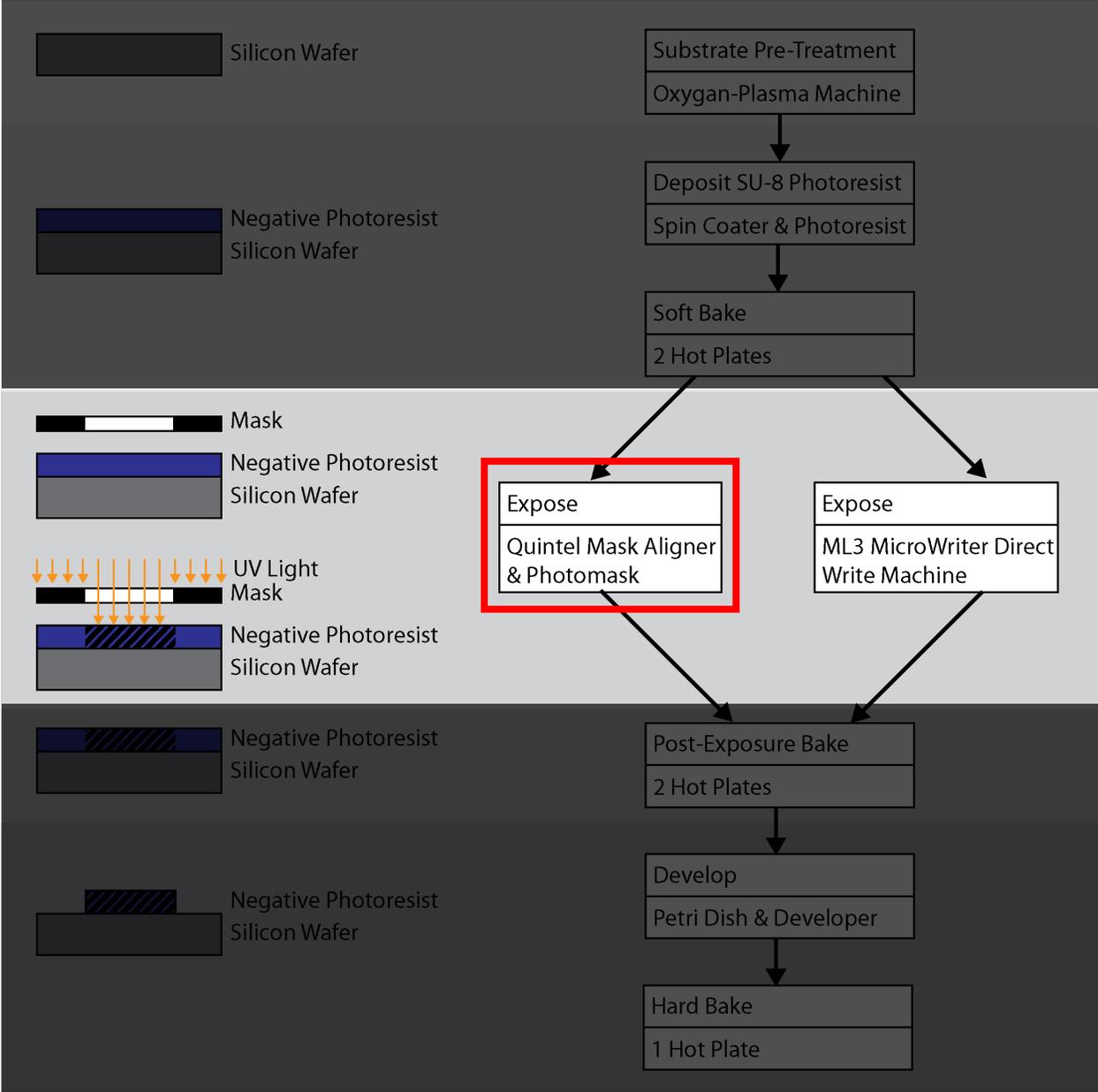






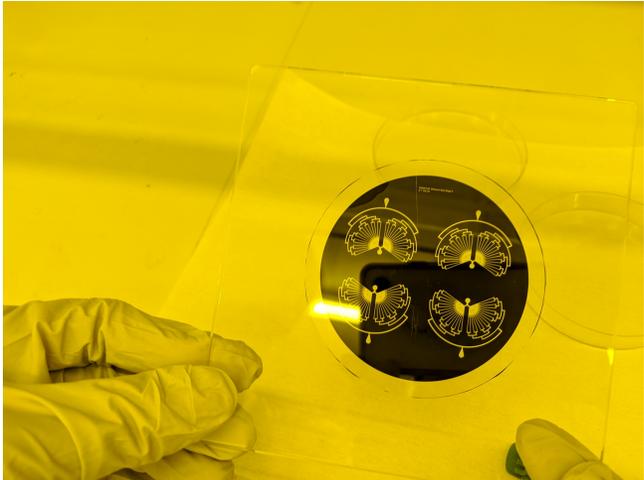
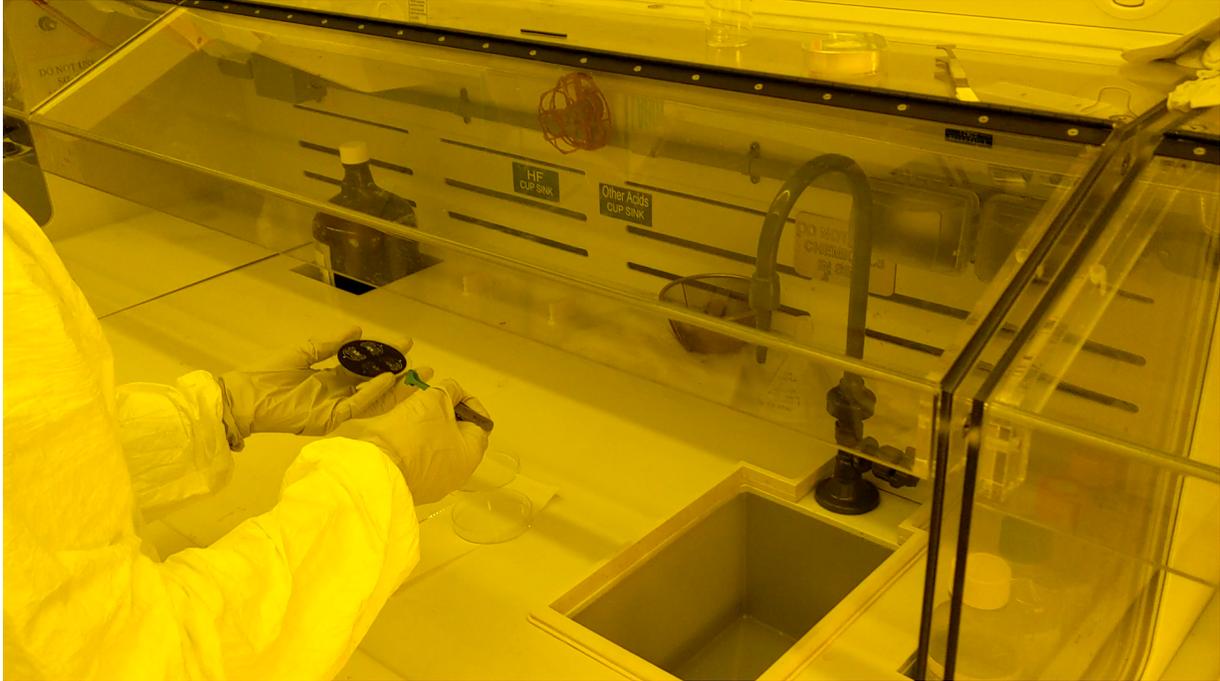












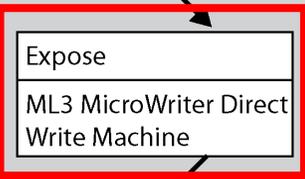












Silicon Wafer

Negative Photoresist
Silicon Wafer

Mask

Negative Photoresist
Silicon Wafer

UV Light
Mask

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

Expose
Quintel Mask Aligner
& Photomask

Expose
ML3 MicroWriter Direct
Write Machine

Post-Exposure Bake
2 Hot Plates

Develop
Petri Dish & Developer

Hard Bake
1 Hot Plate





Silicon Wafer

Negative Photoresist
Silicon Wafer

Mask

Negative Photoresist
Silicon Wafer

UV Light
Mask

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

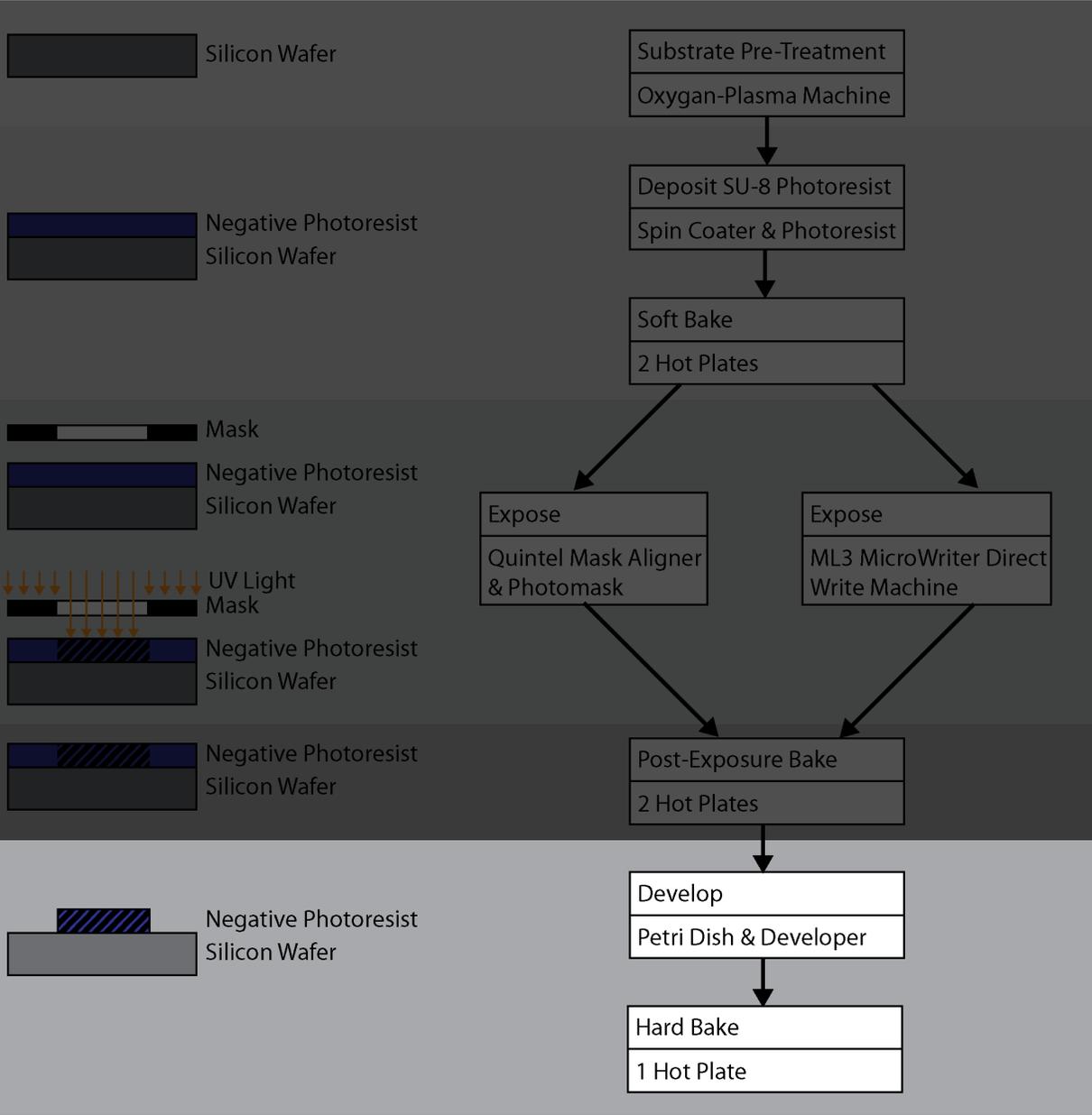
Expose
Quintel Mask Aligner
& Photomask

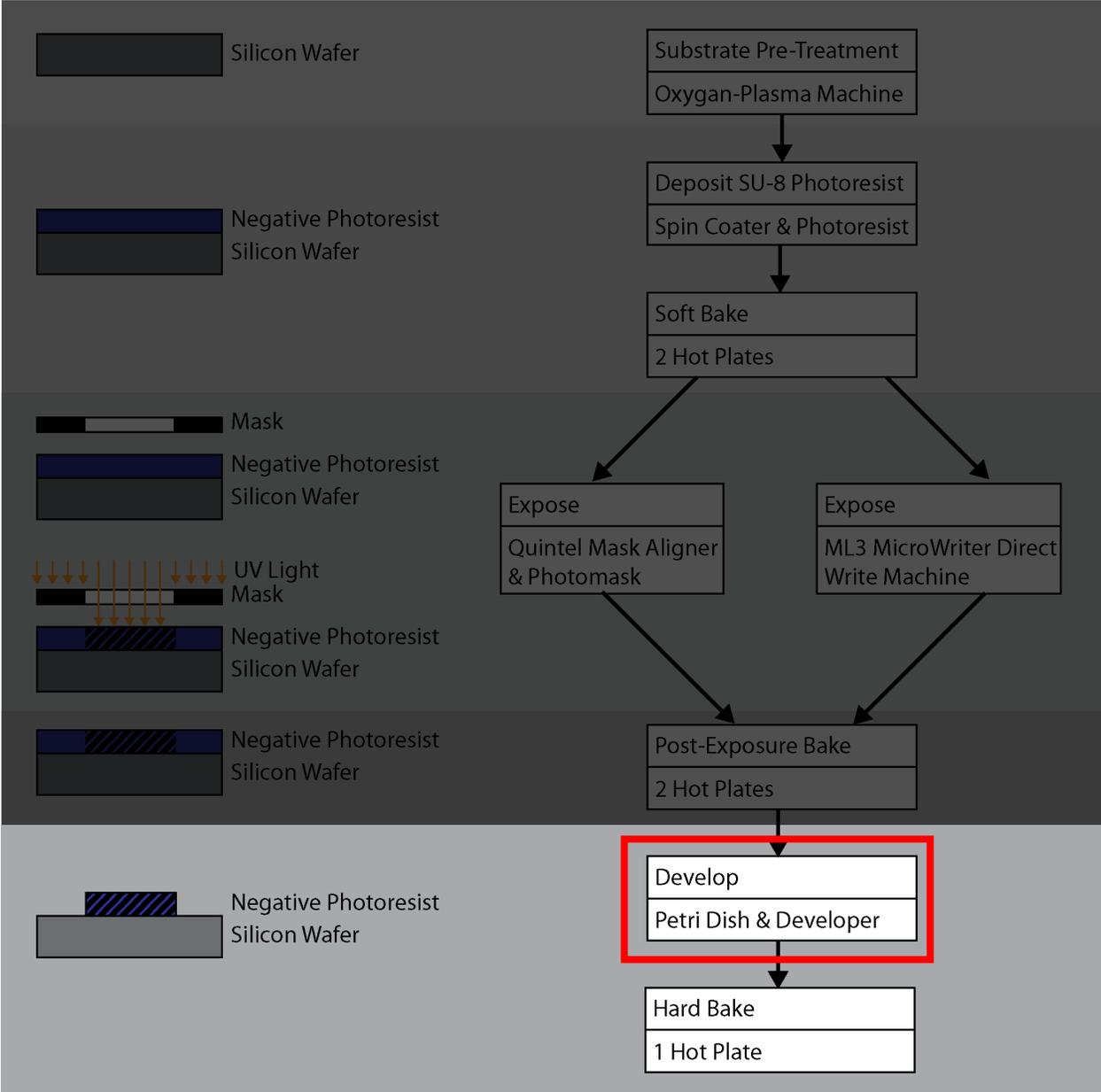
Expose
ML3 MicroWriter Direct
Write Machine

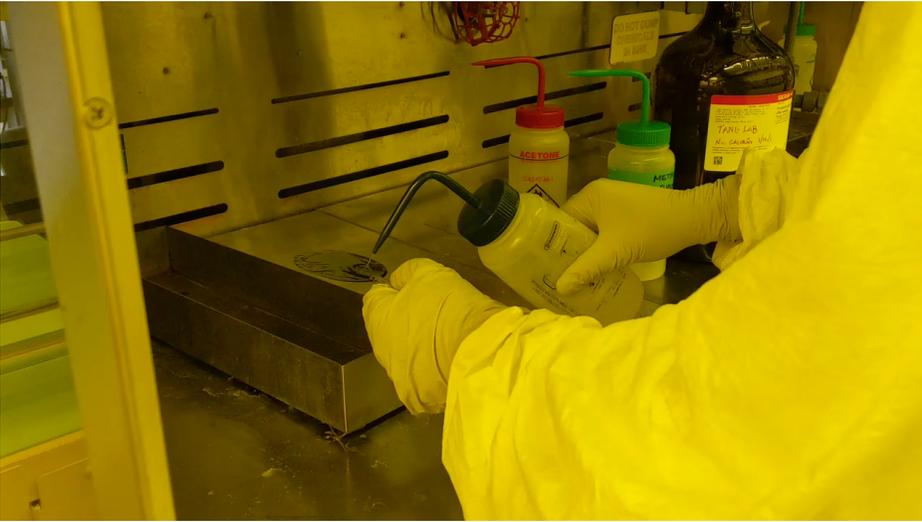
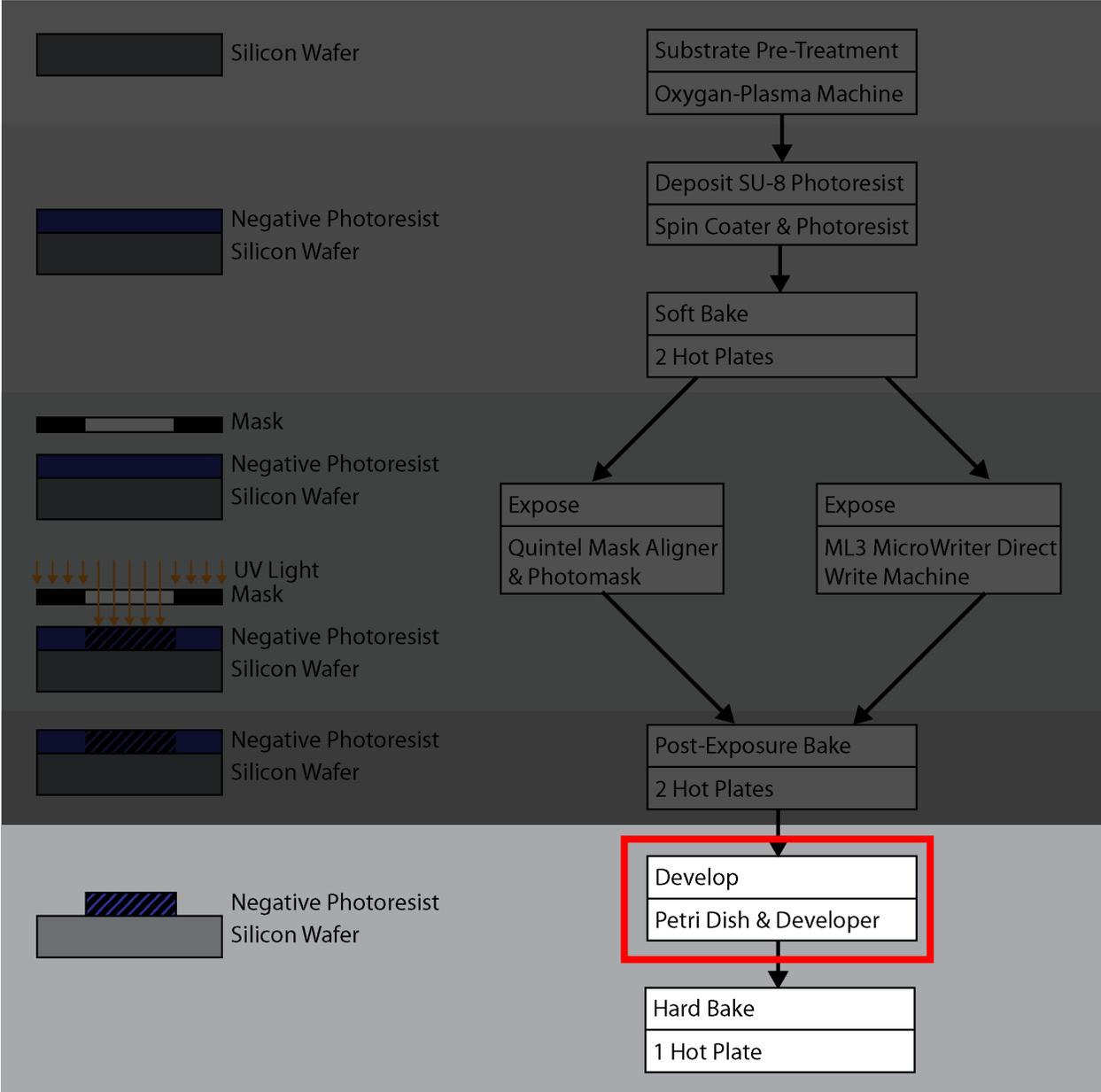
Post-Exposure Bake
2 Hot Plates

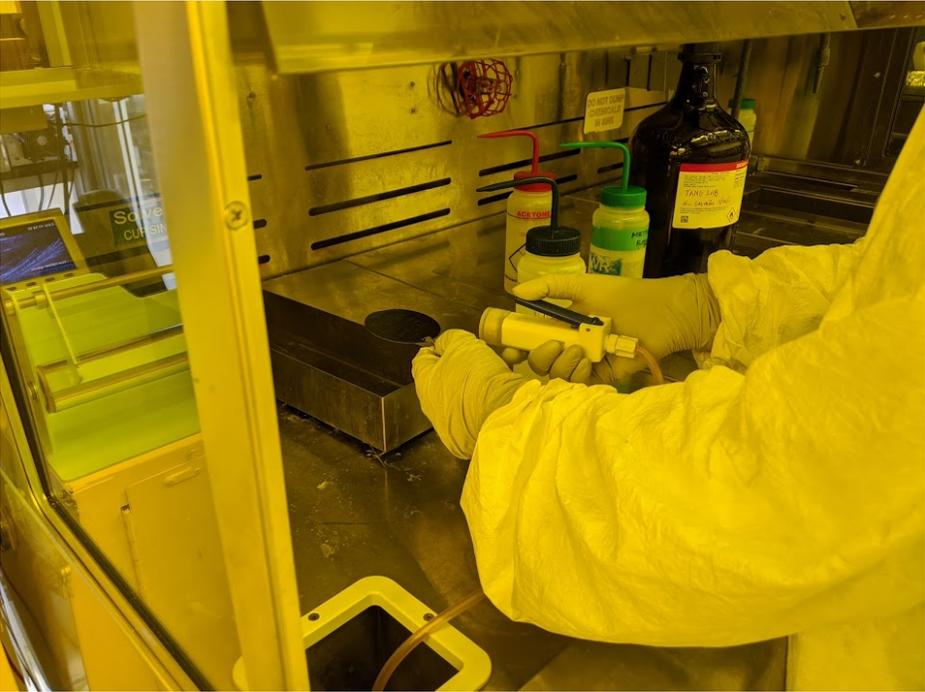
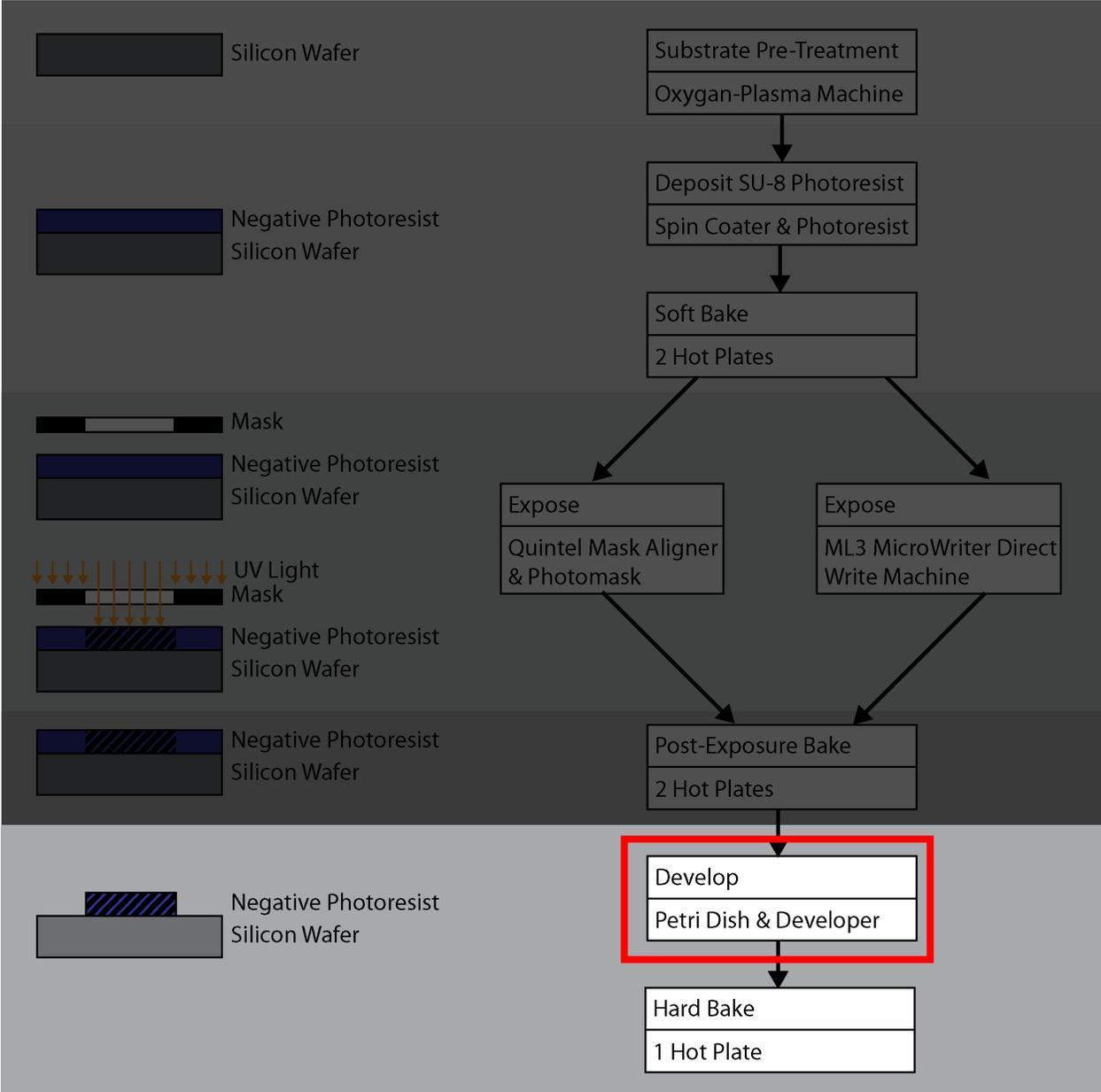
Develop
Petri Dish & Developer

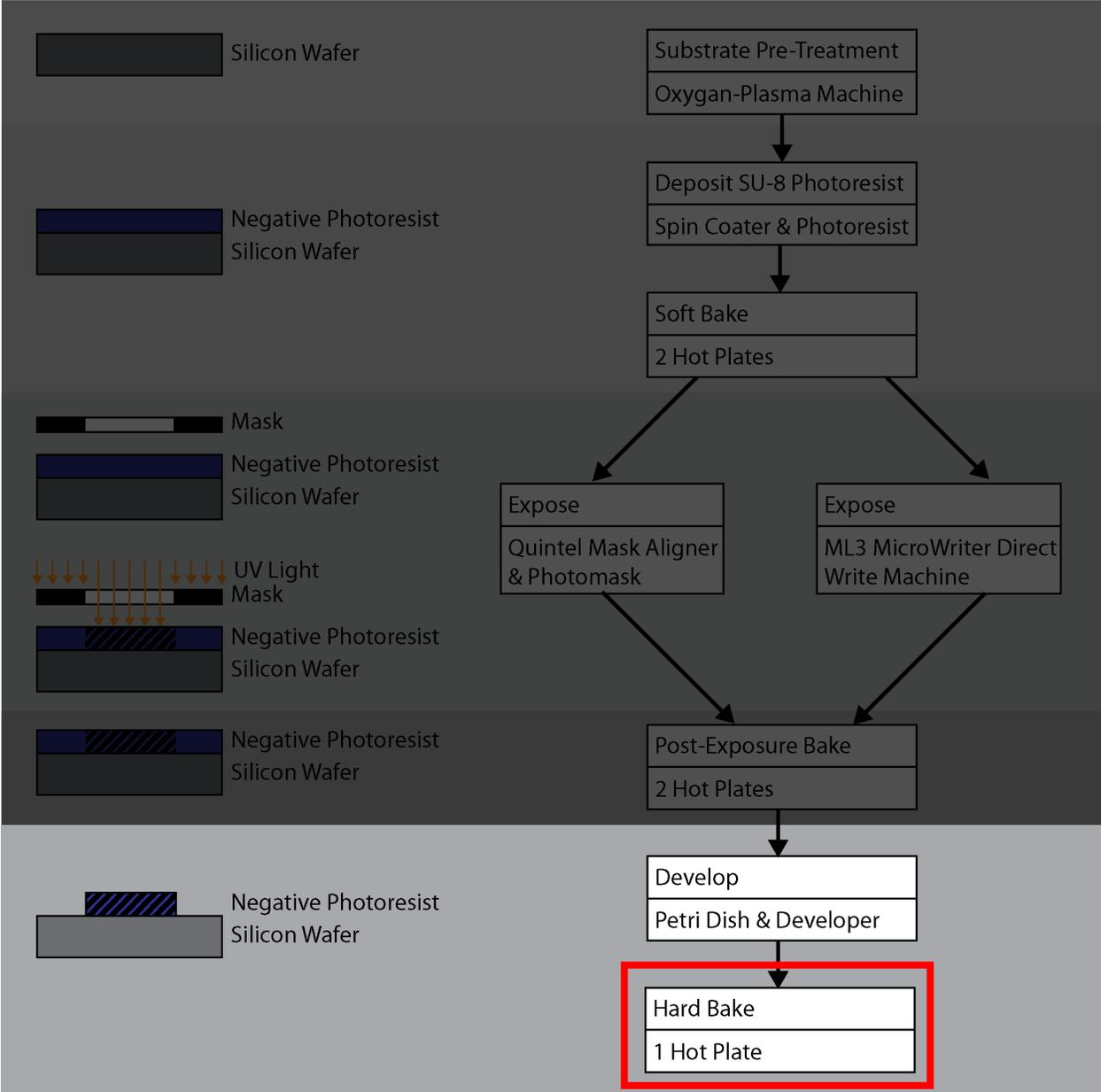
Hard Bake
1 Hot Plate











Silicon Wafer

Negative Photoresist
Silicon Wafer

Mask

Negative Photoresist
Silicon Wafer

UV Light
Mask

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Negative Photoresist
Silicon Wafer

Substrate Pre-Treatment
Oxygen-Plasma Machine

Deposit SU-8 Photoresist
Spin Coater & Photoresist

Soft Bake
2 Hot Plates

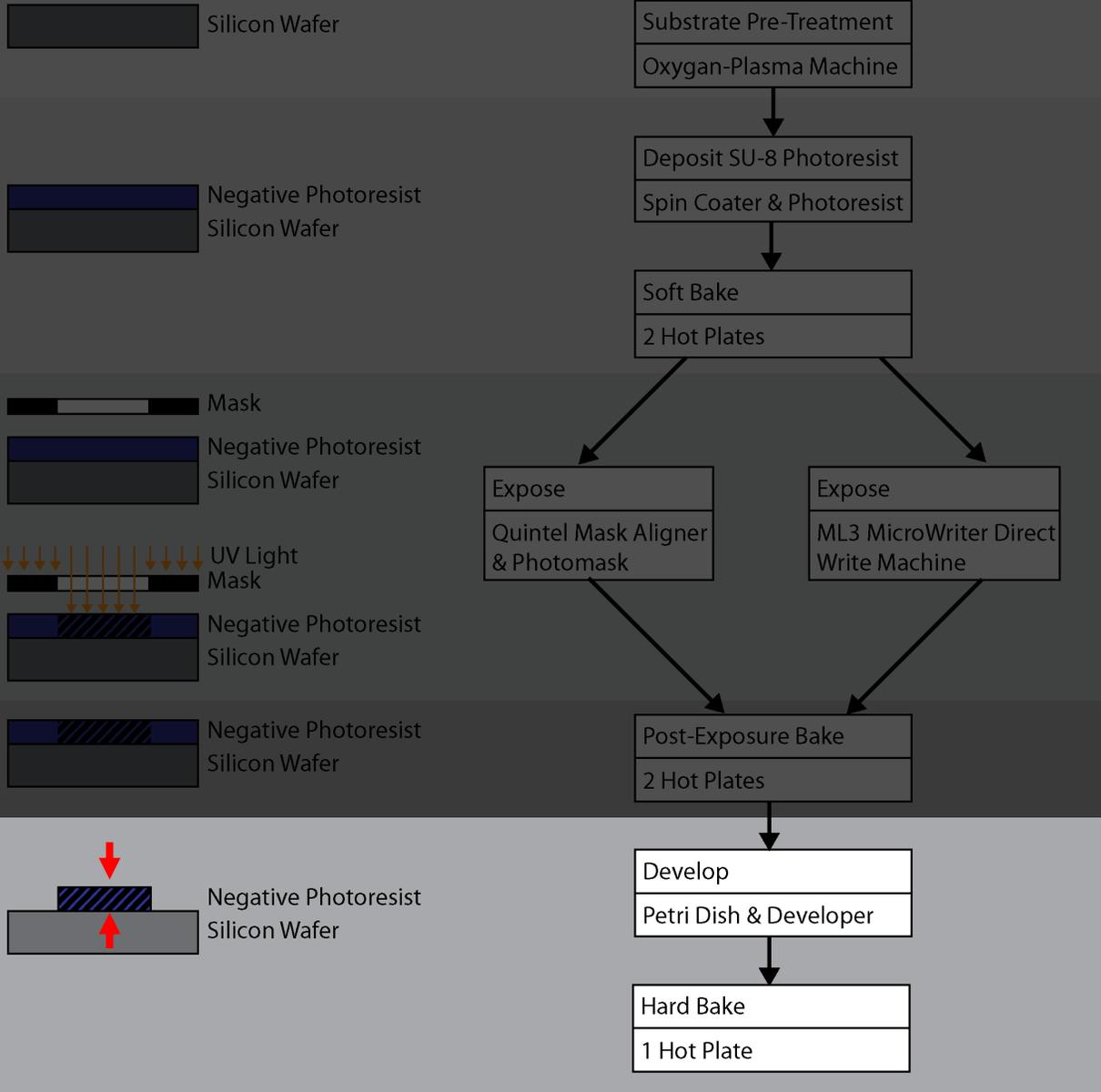
Expose
Quintel Mask Aligner
& Photomask

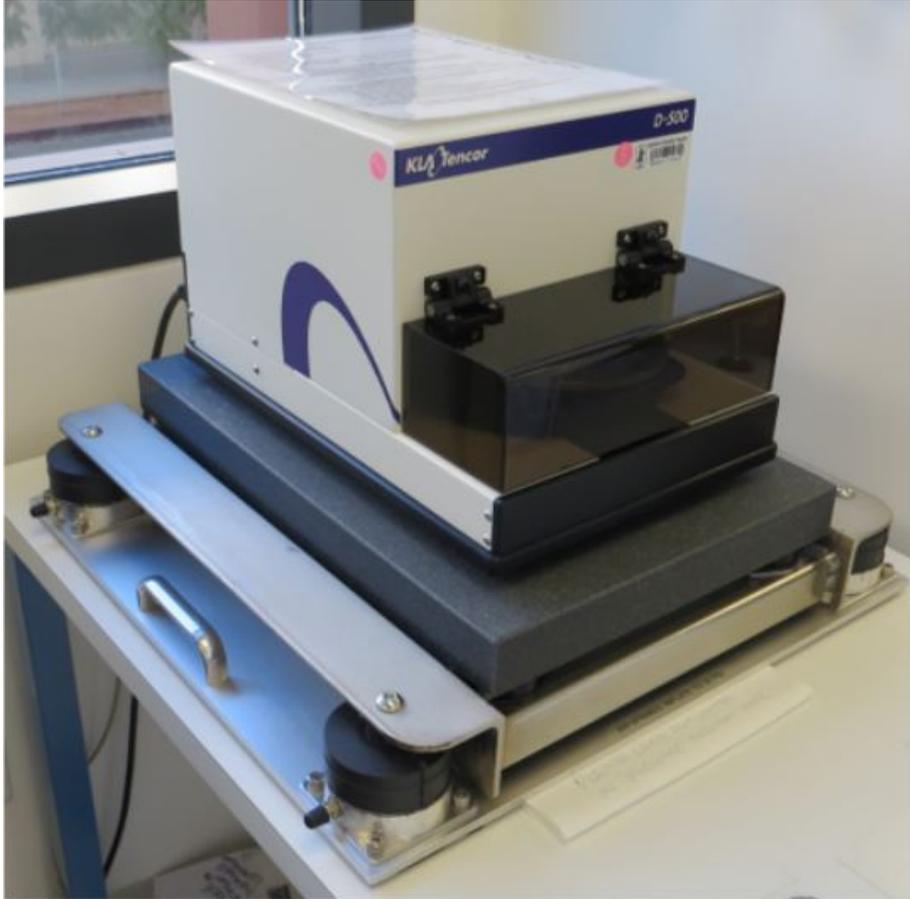
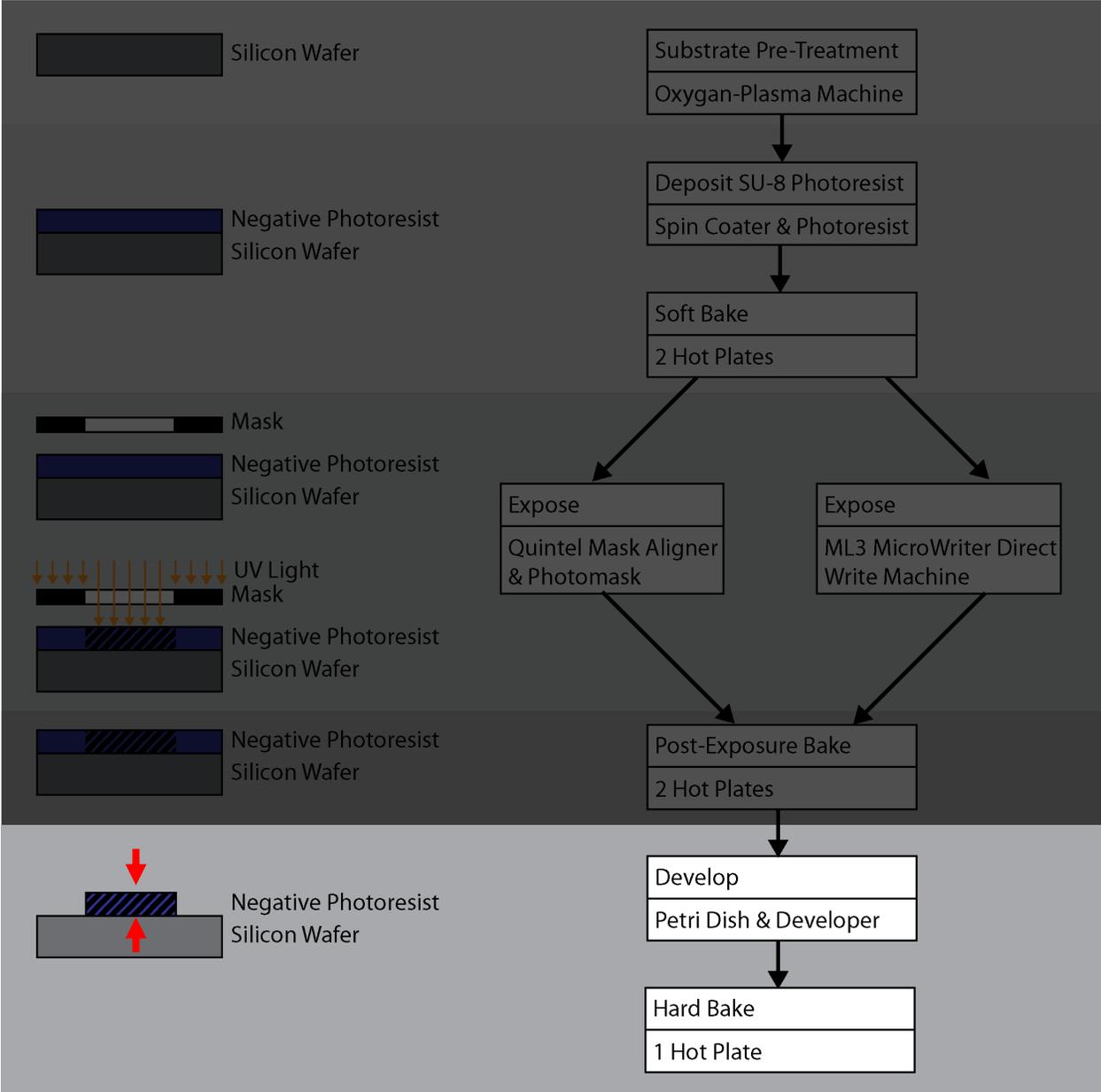
Expose
ML3 MicroWriter Direct
Write Machine

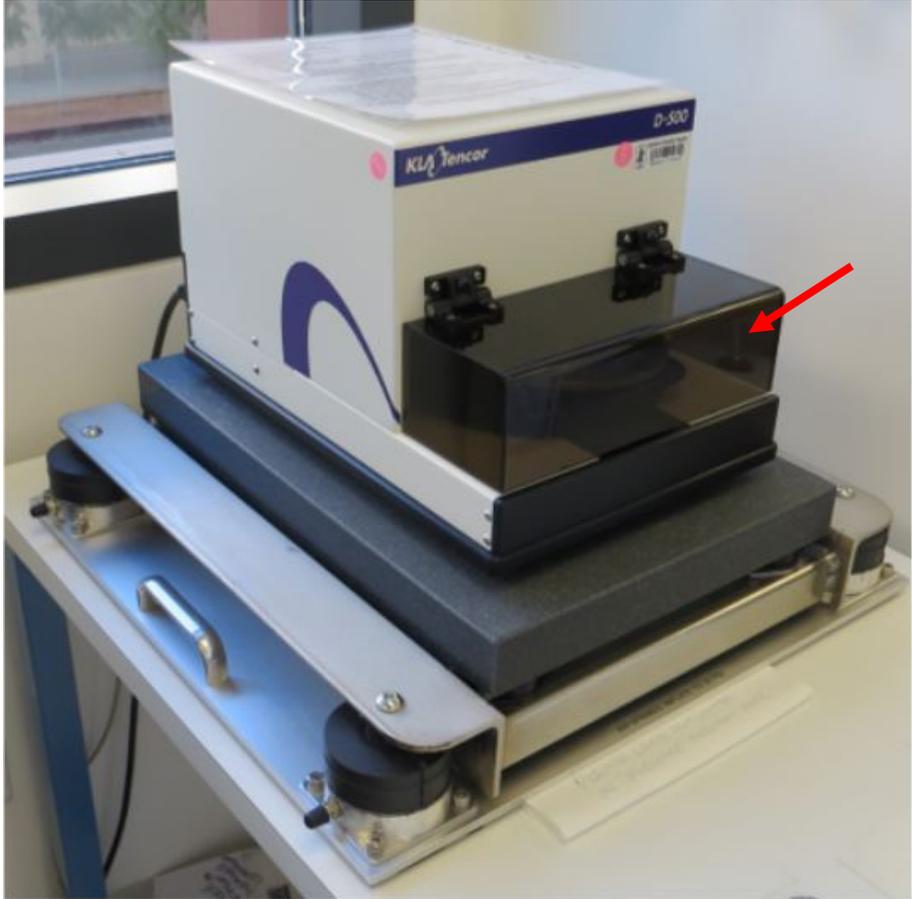
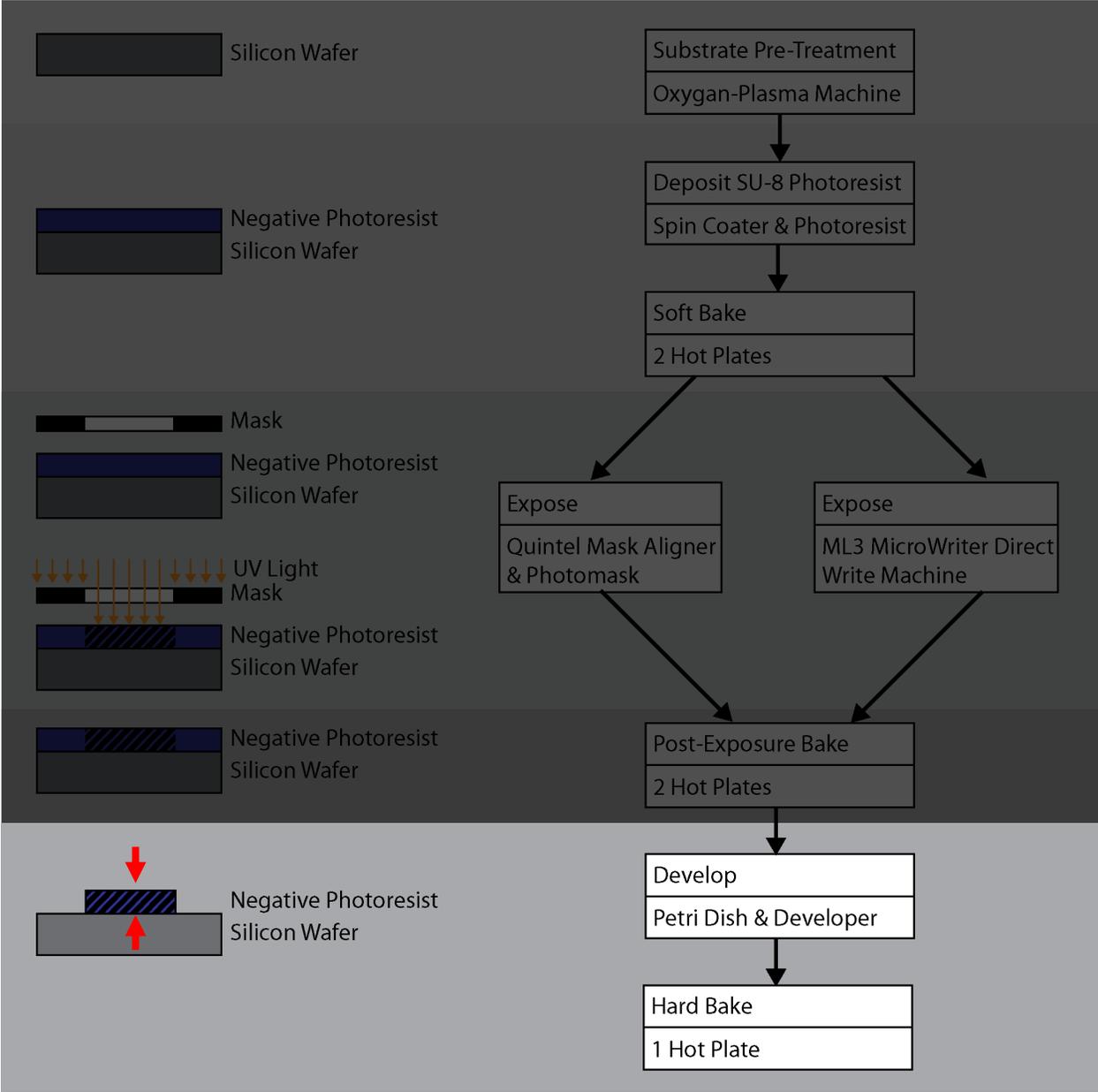
Post-Exposure Bake
2 Hot Plates

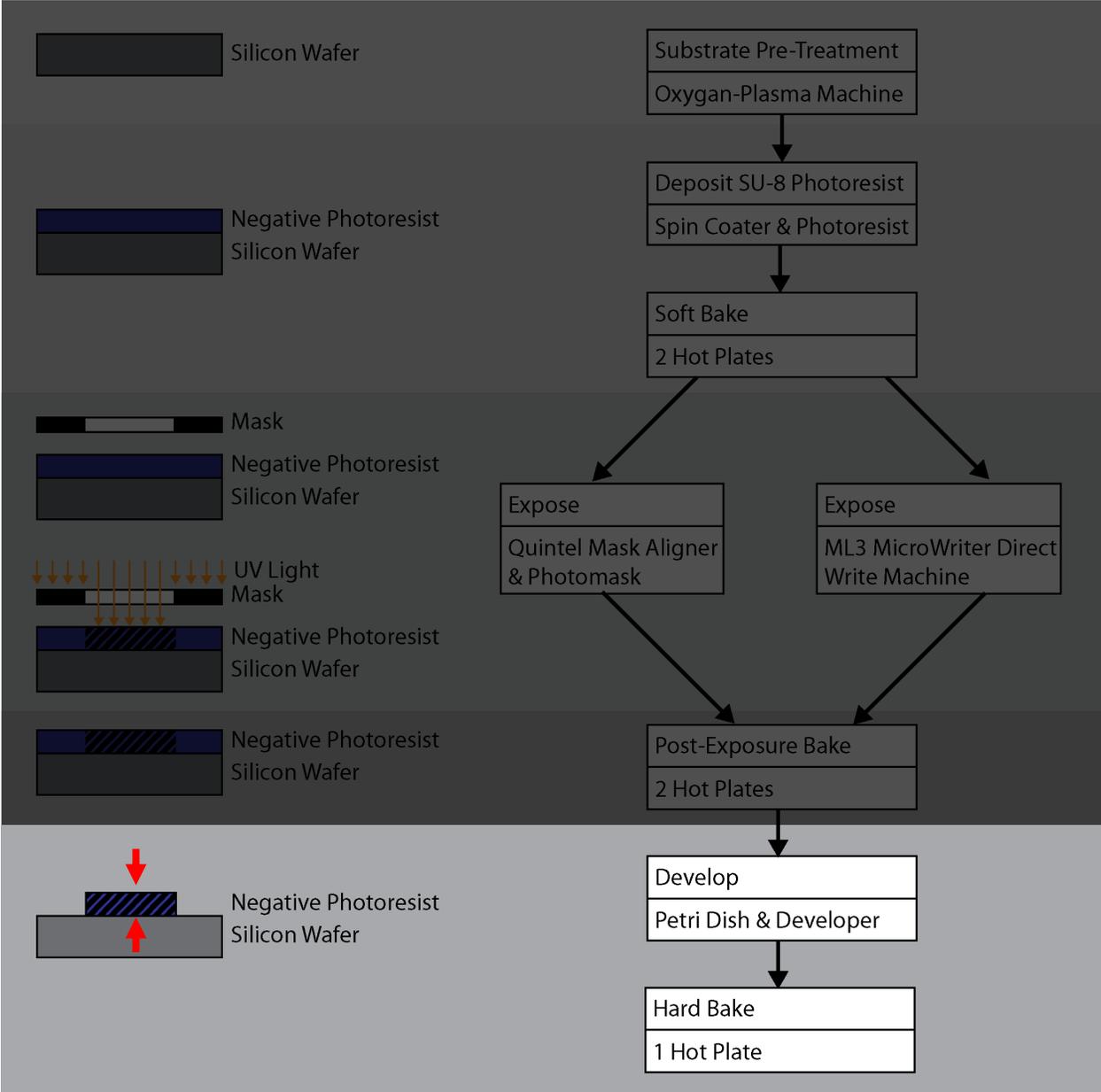
Develop
Petri Dish & Developer

Hard Bake
1 Hot Plate



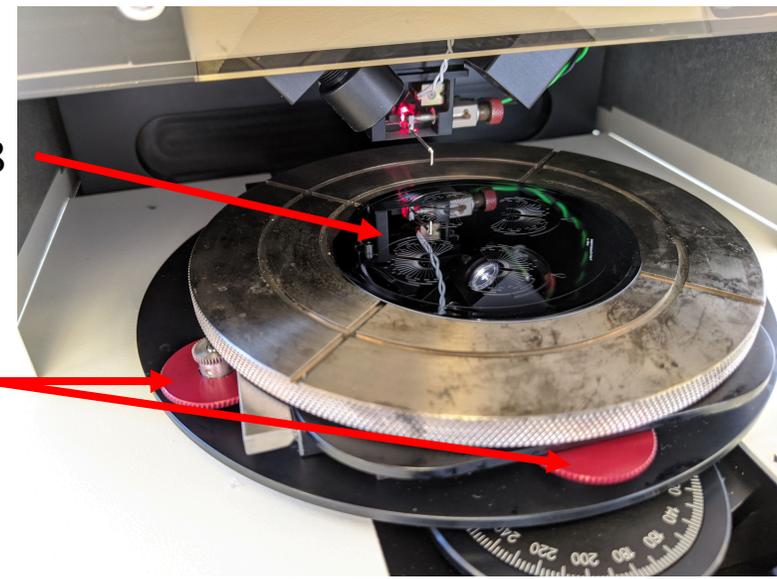


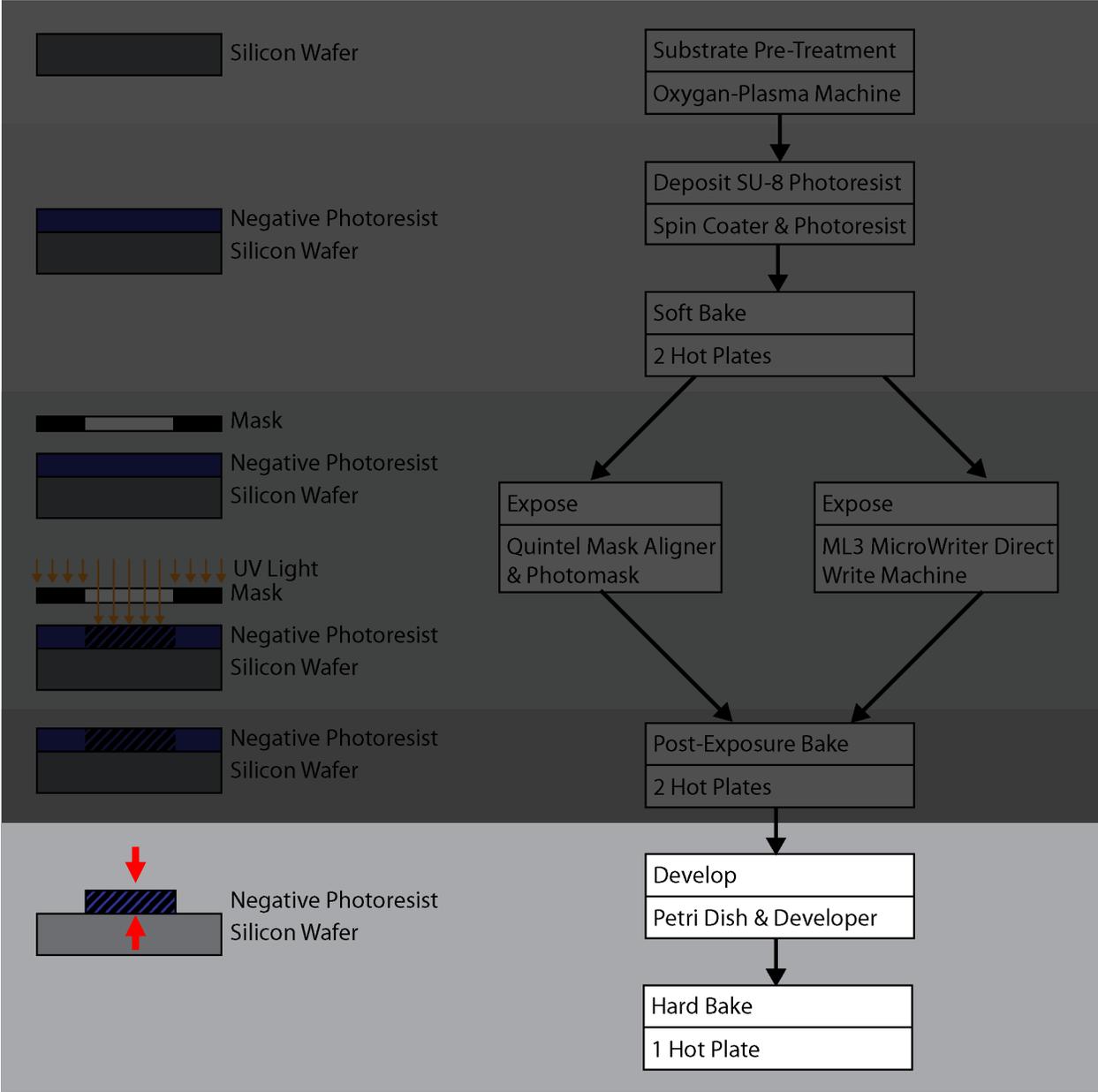




Wafer with SU-8

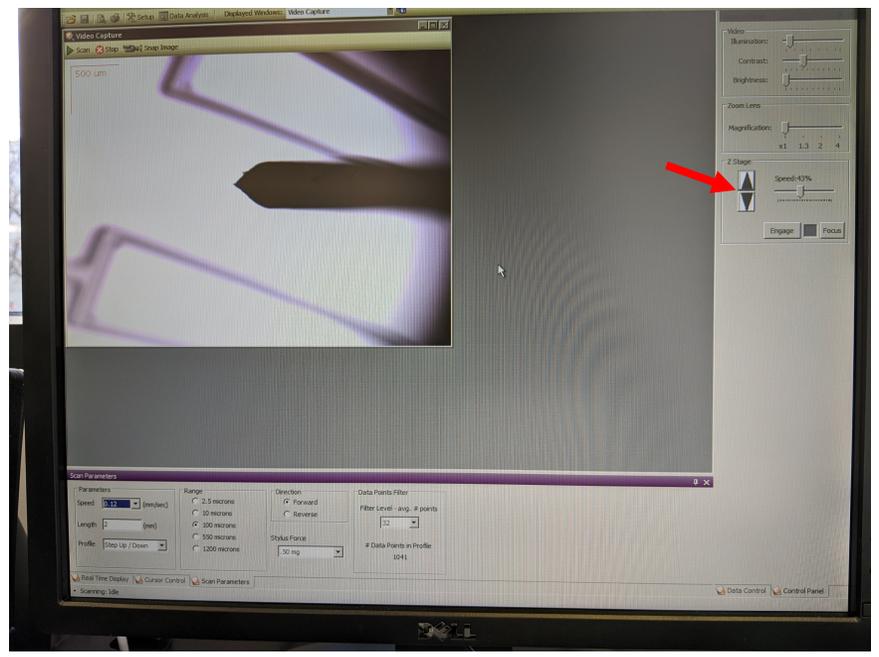
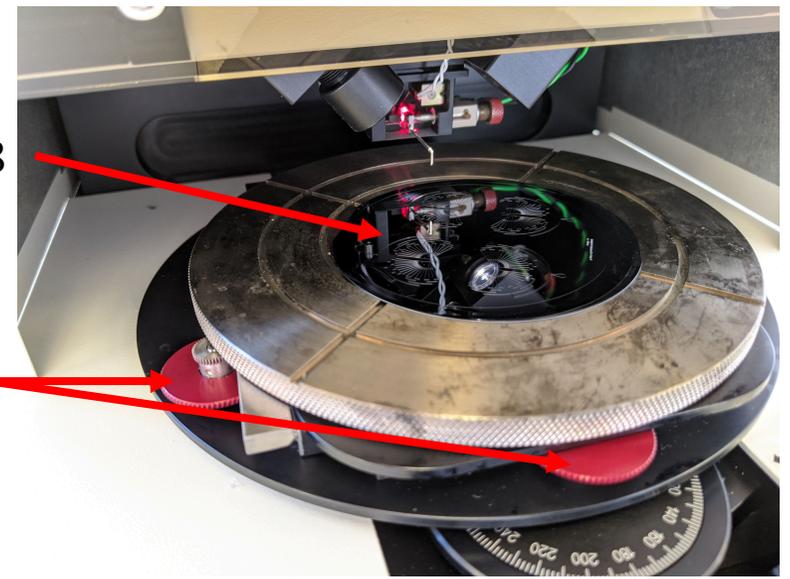
Use red knobs to manually steer in X and Y direction

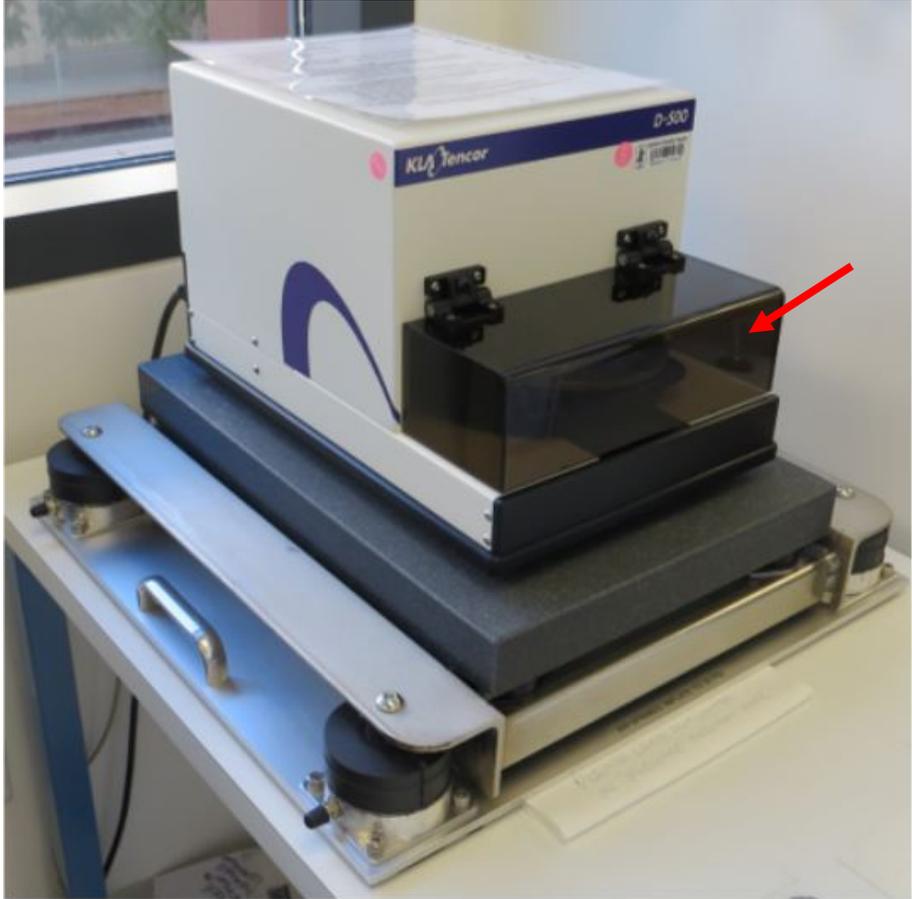
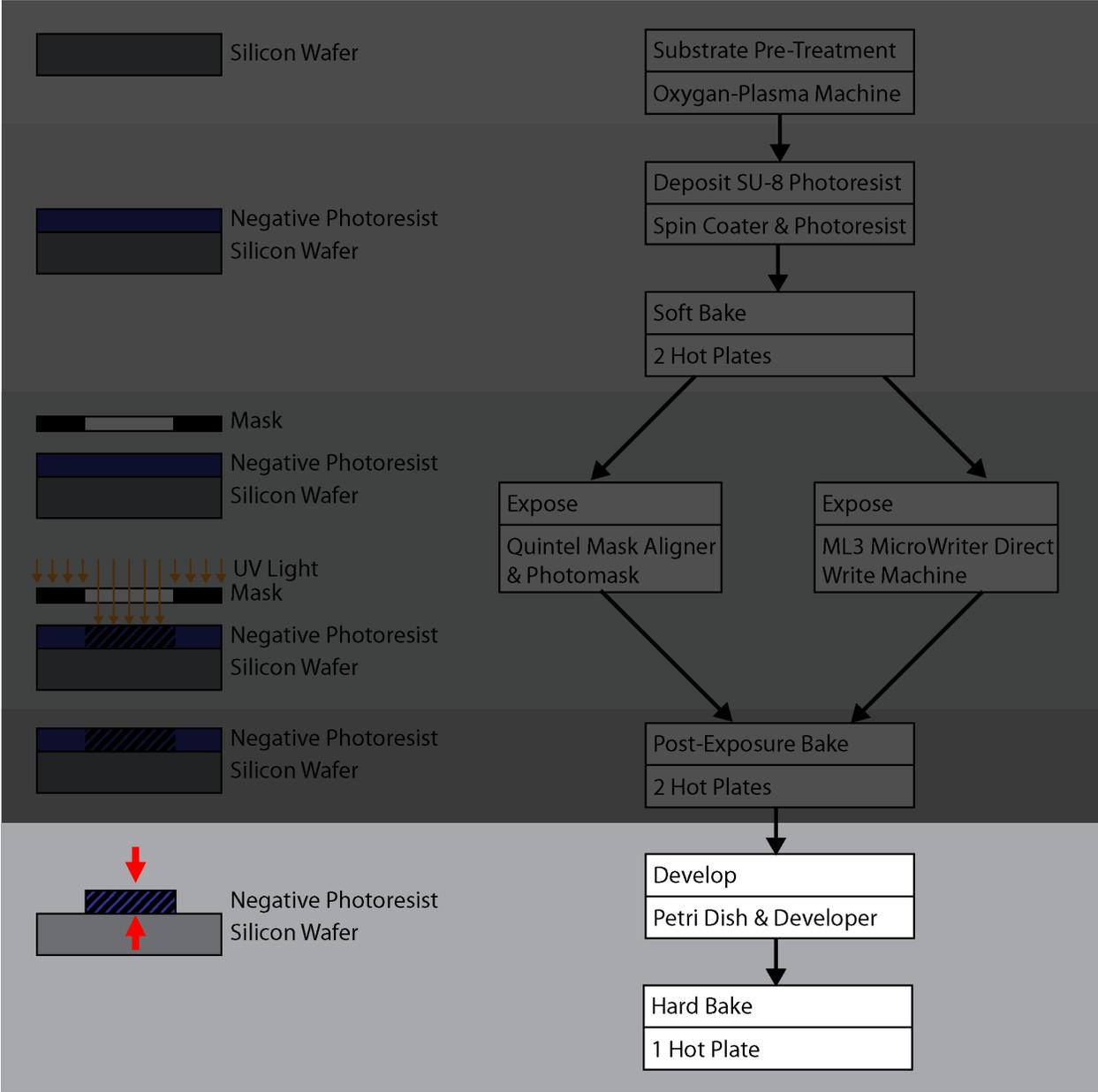


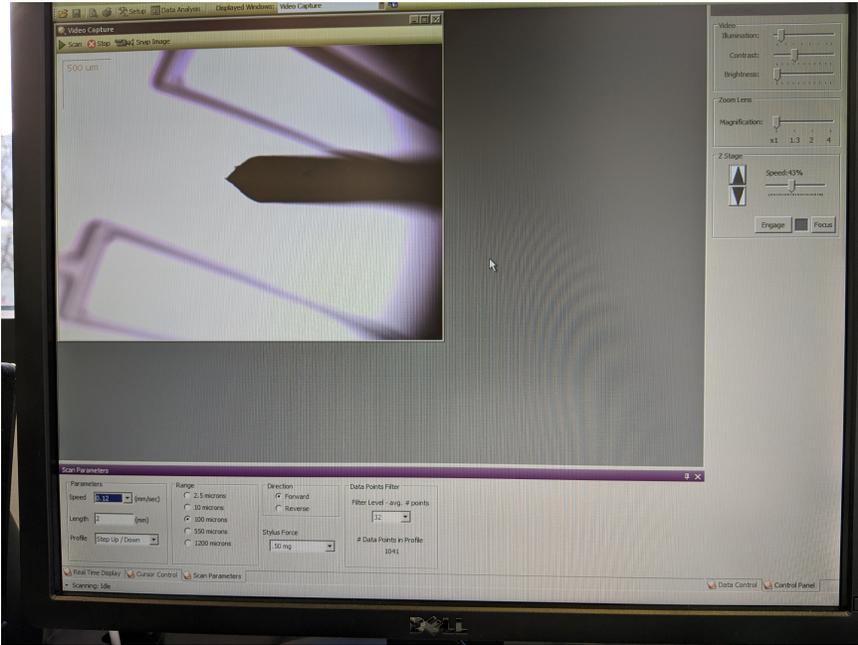
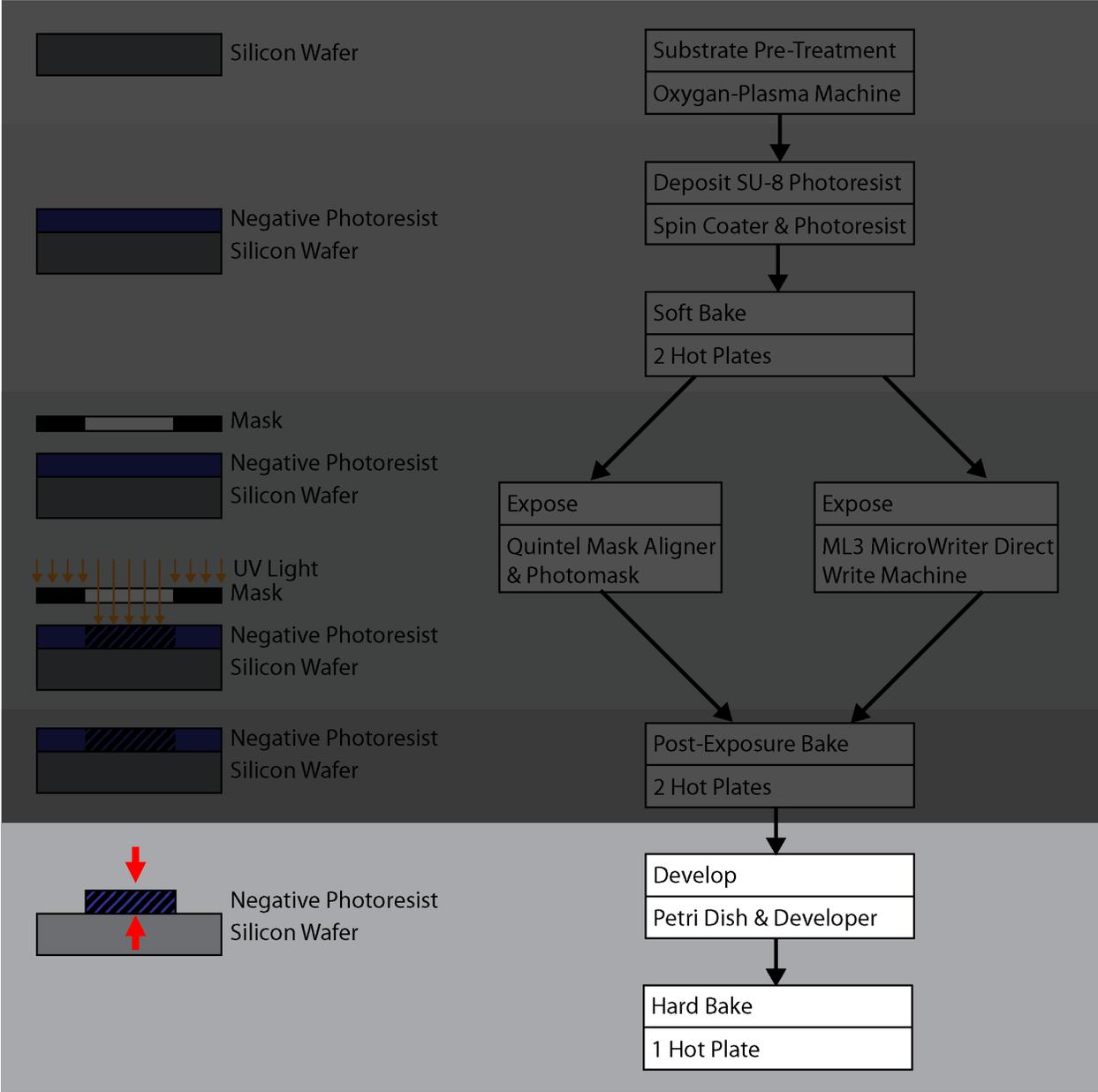


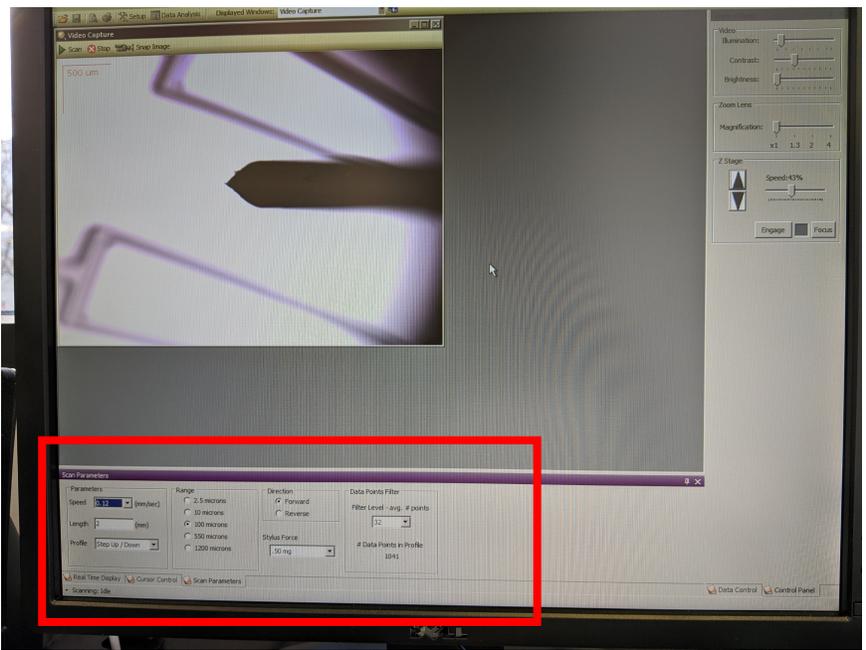
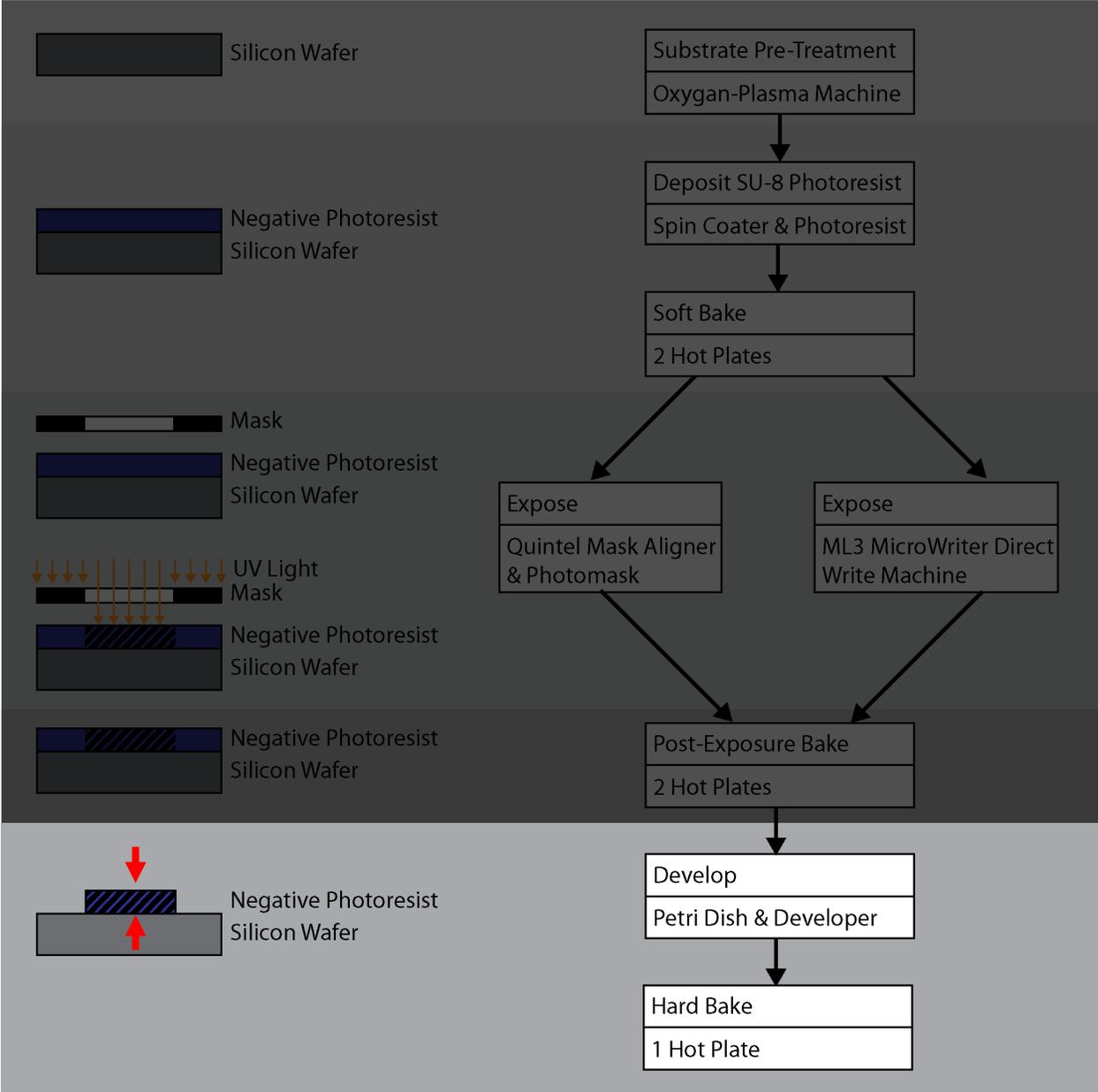
Wafer with SU-8

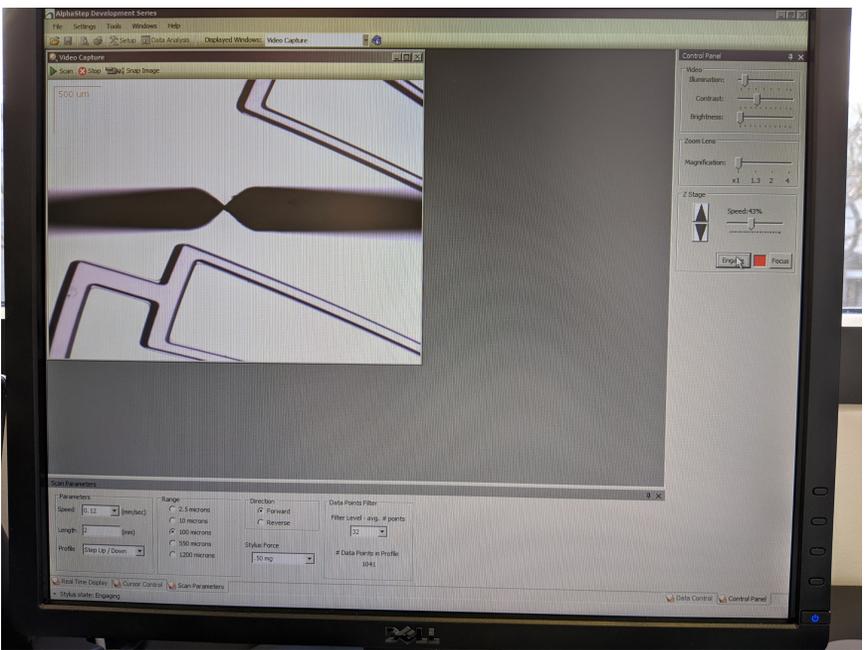
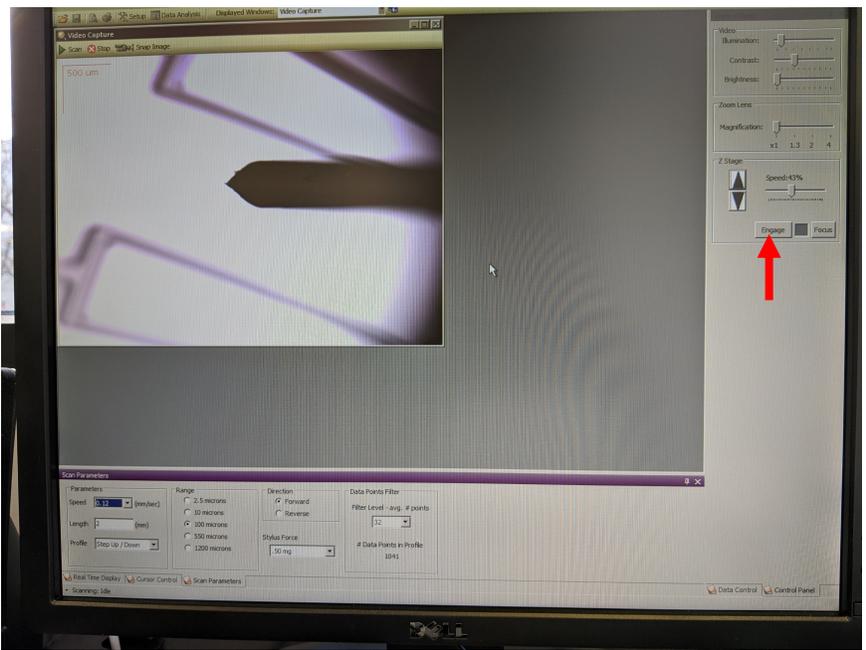
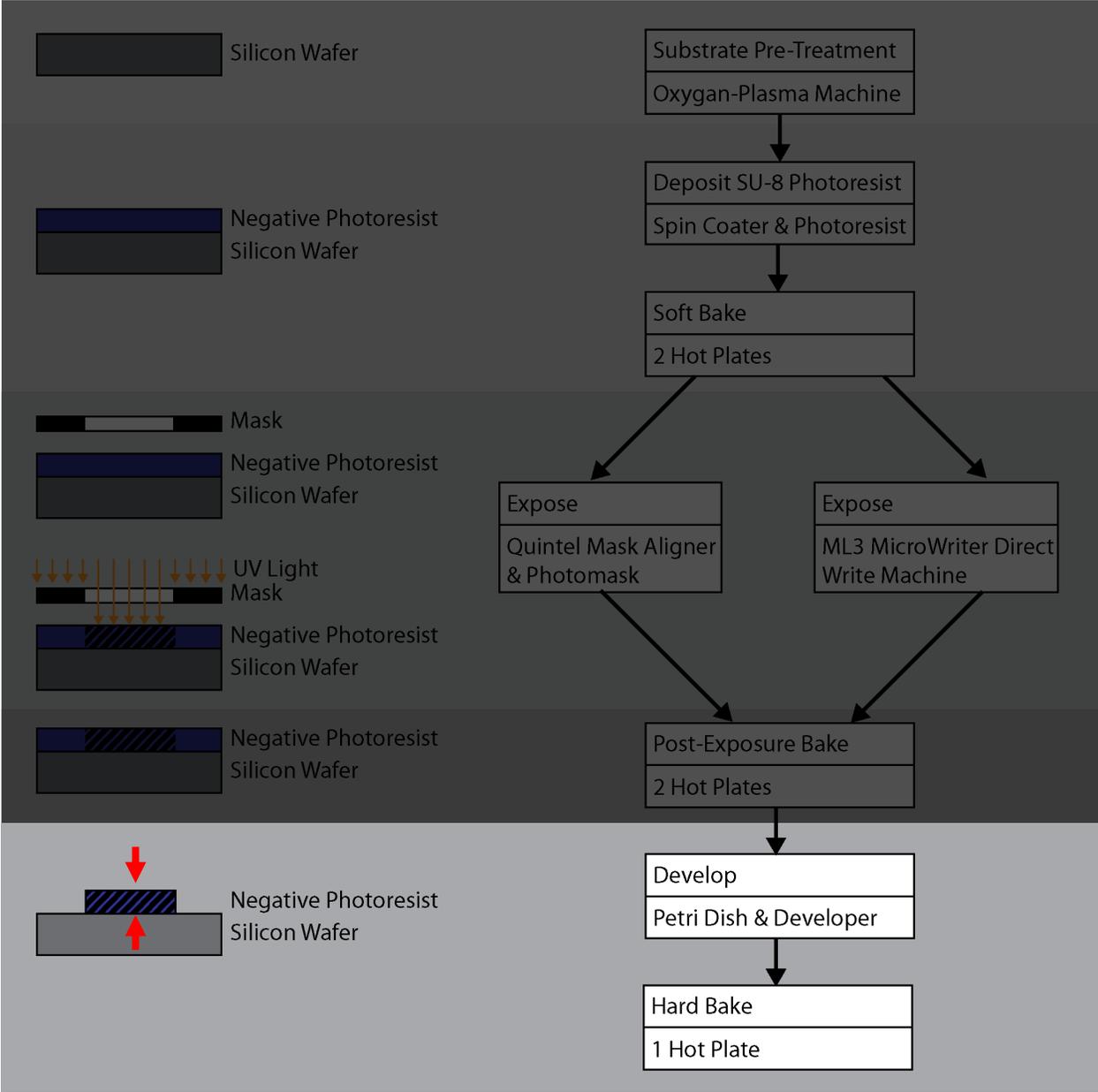
Use red knobs to manually steer in X and Y direction

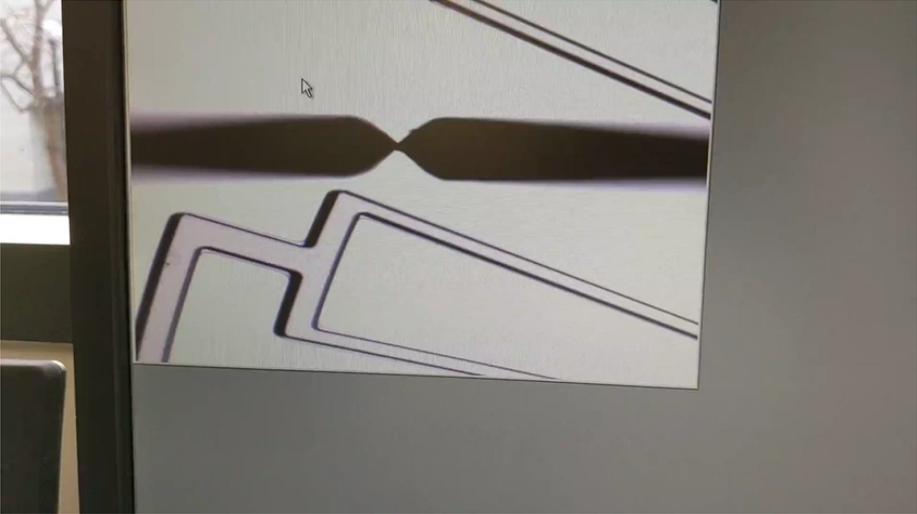
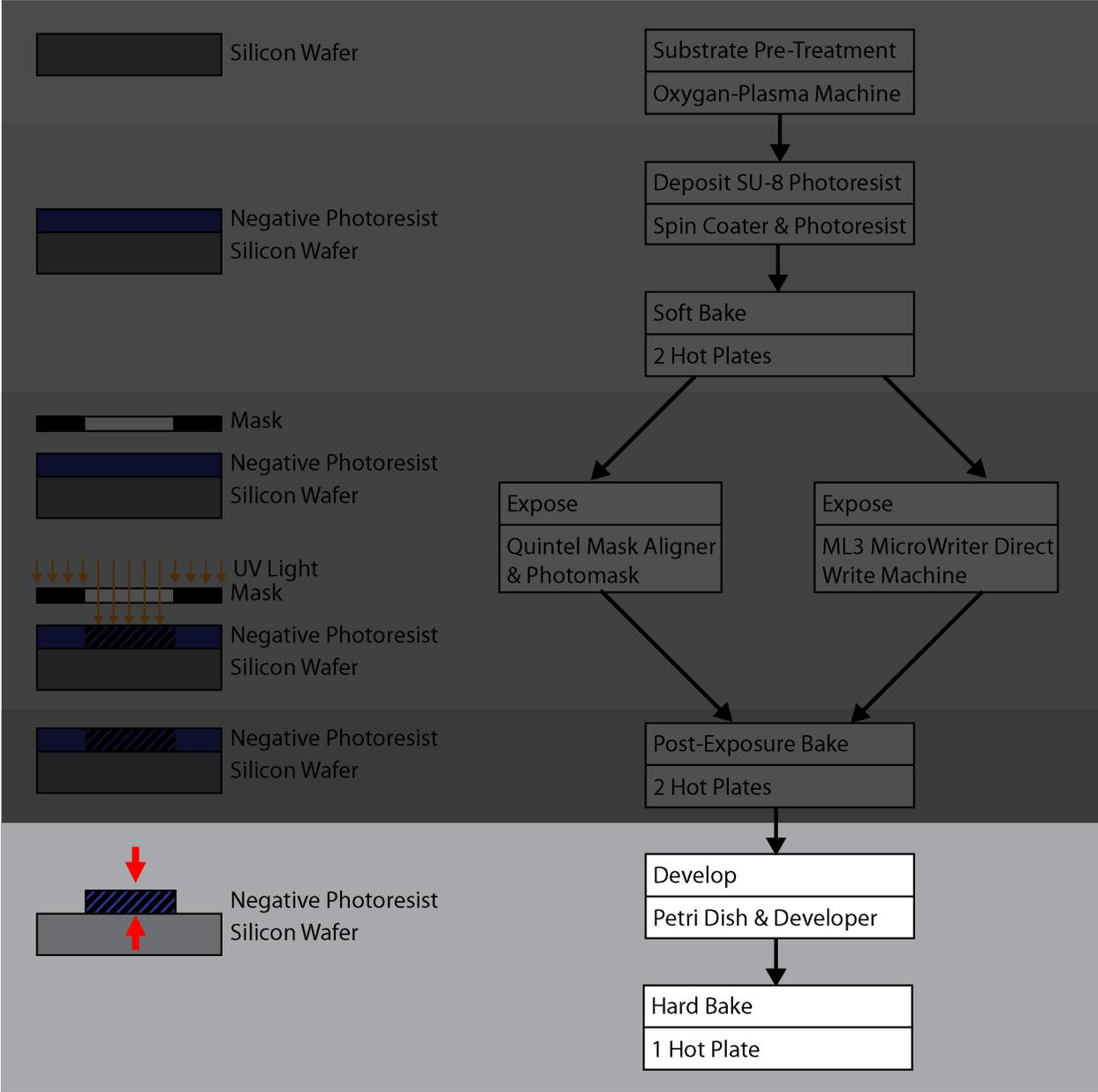


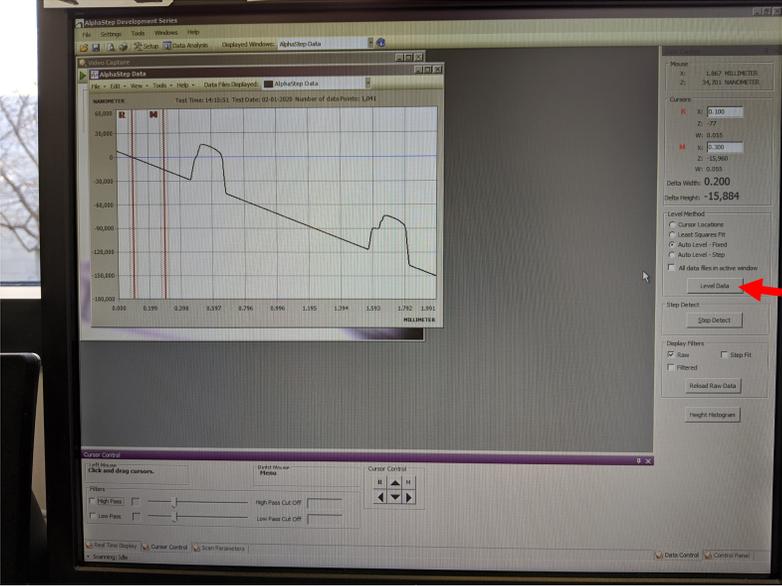
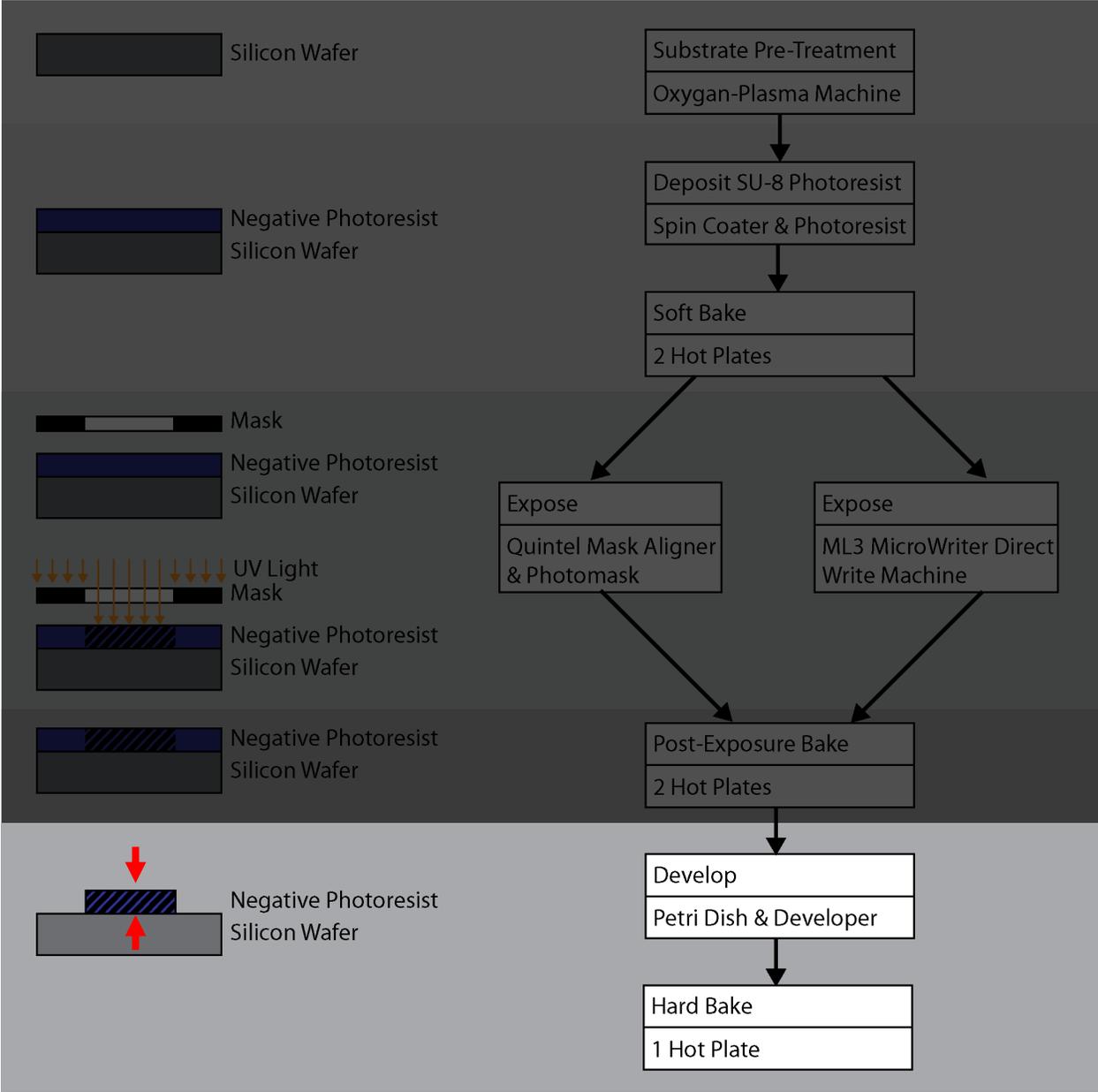


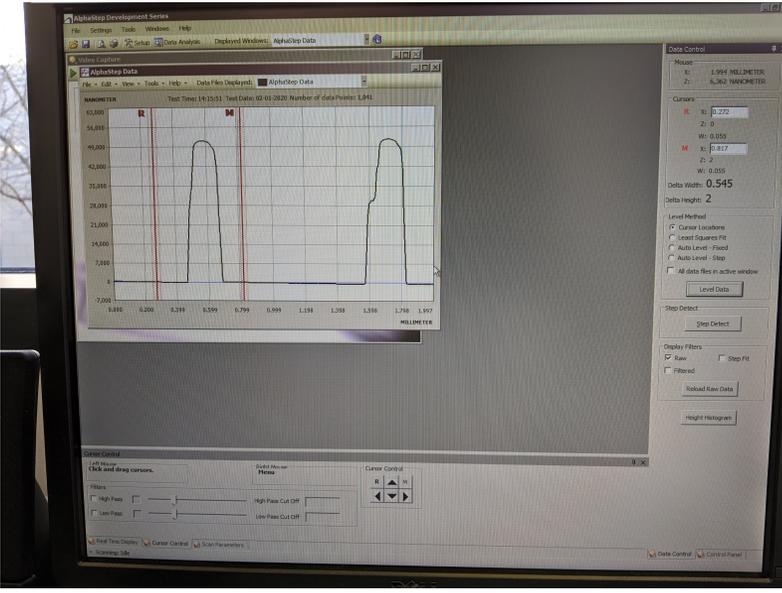
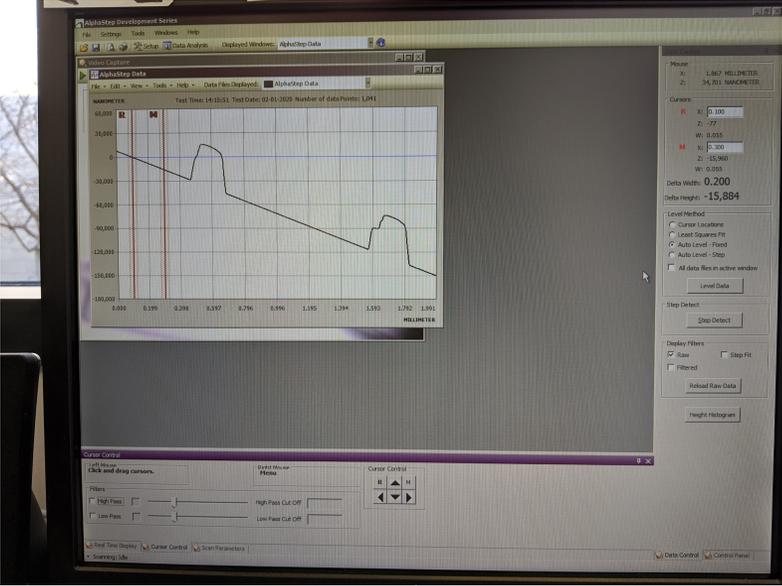
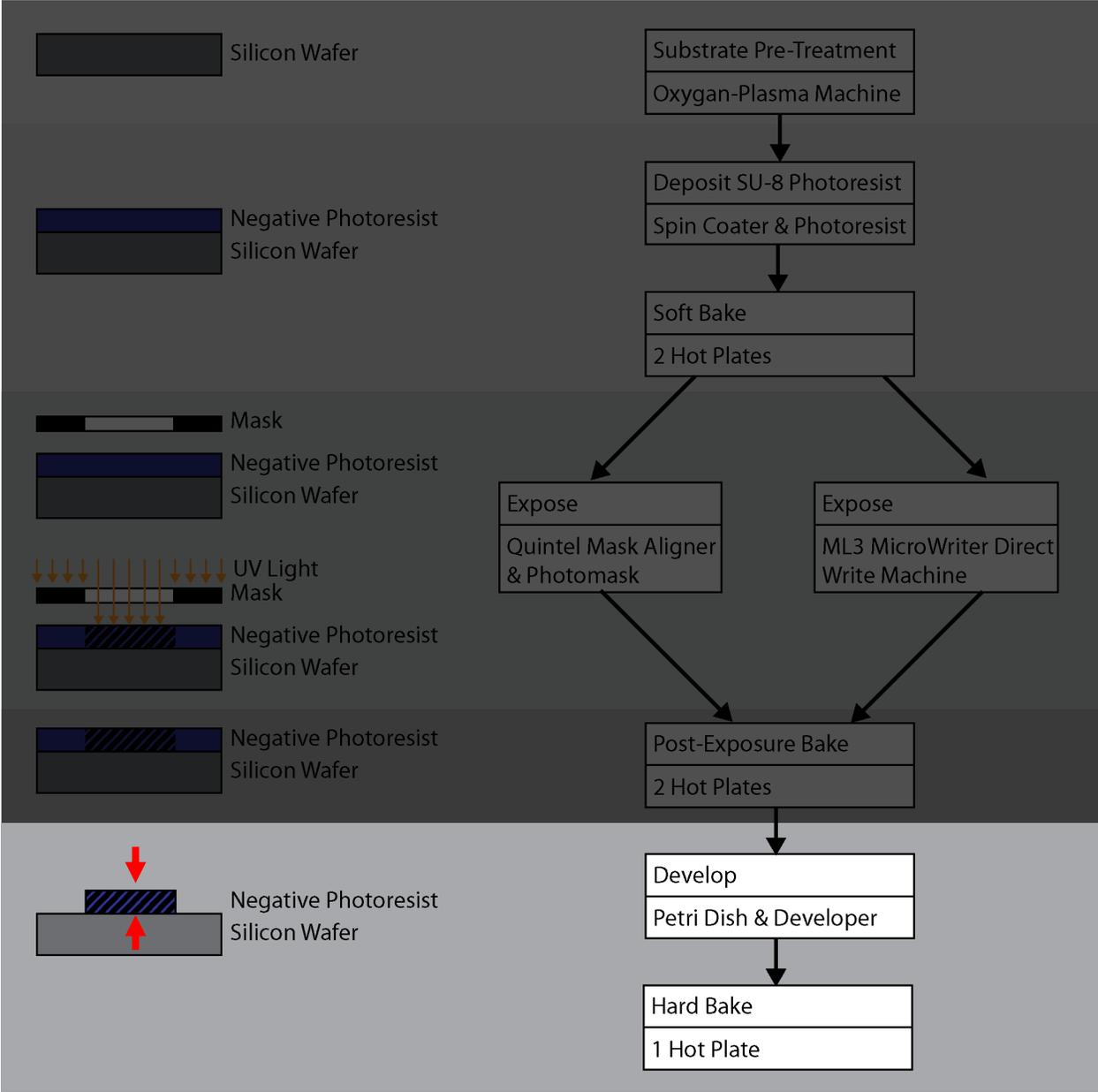


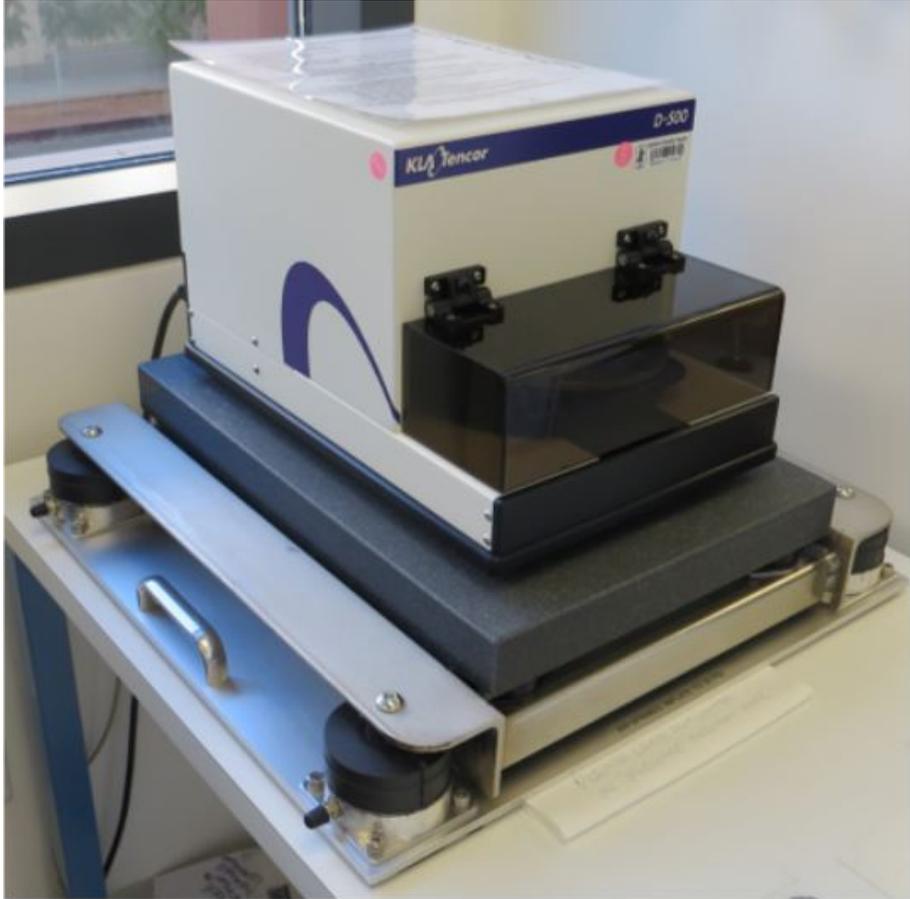
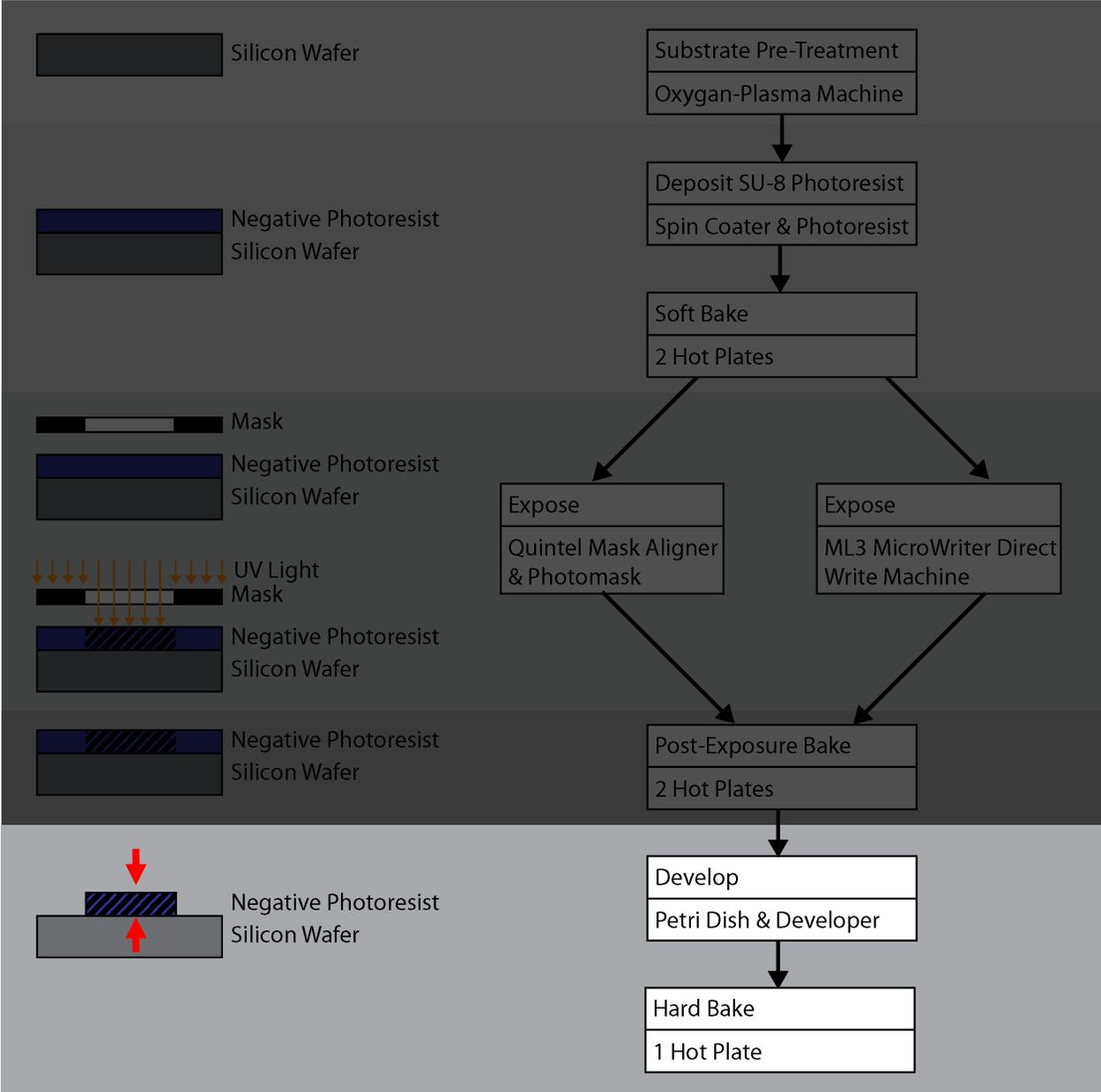




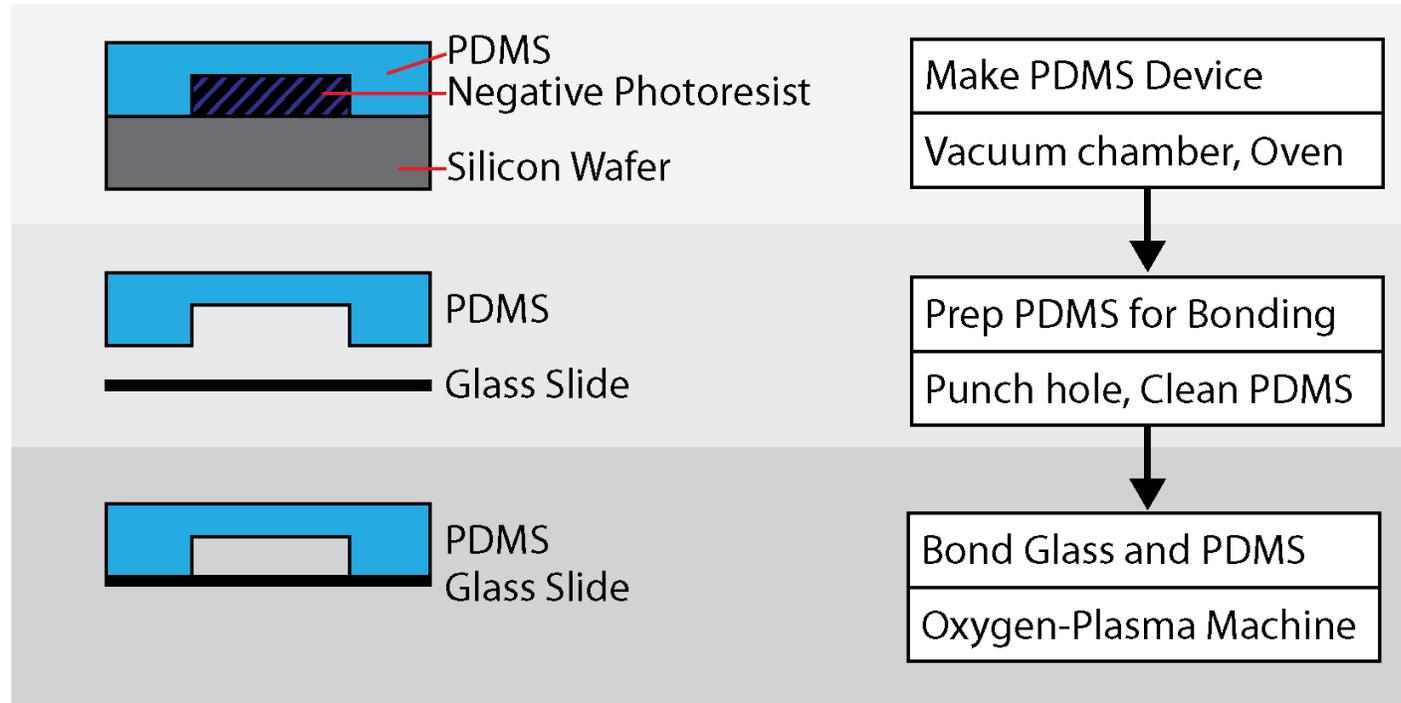




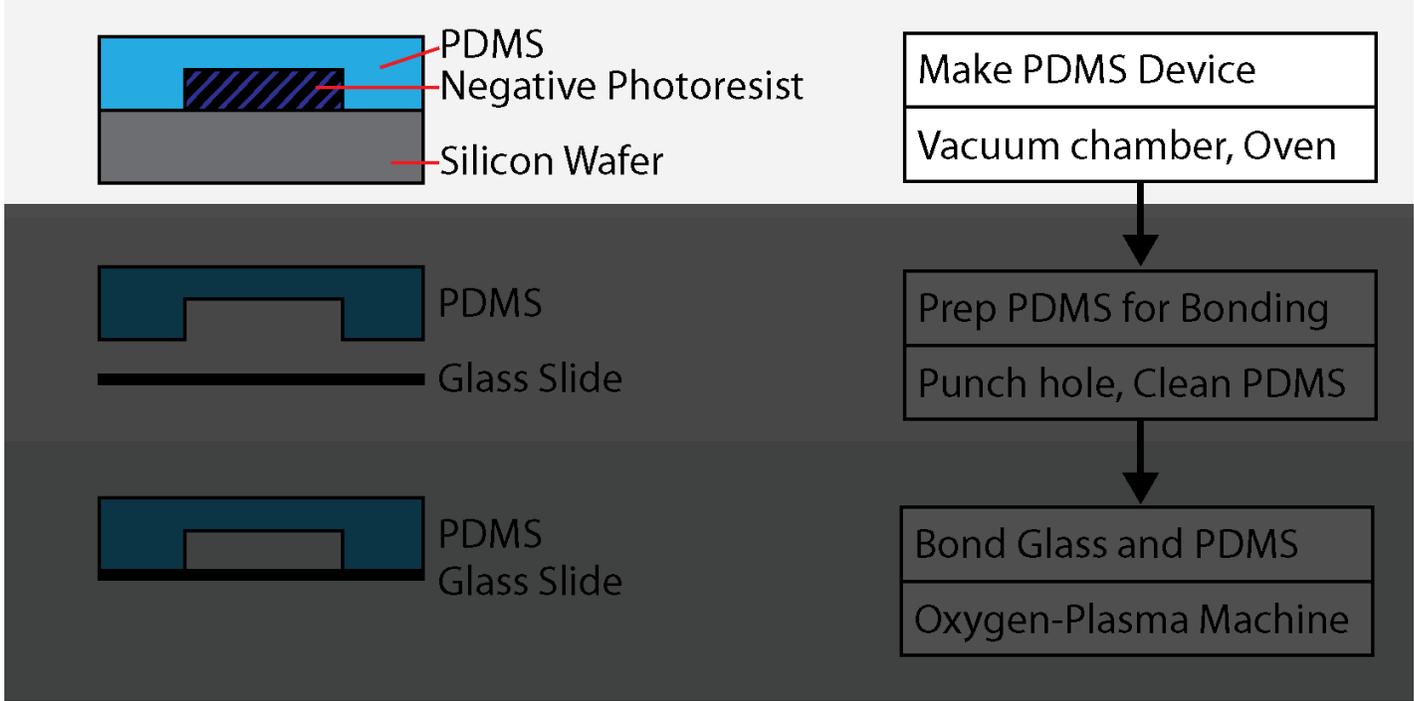




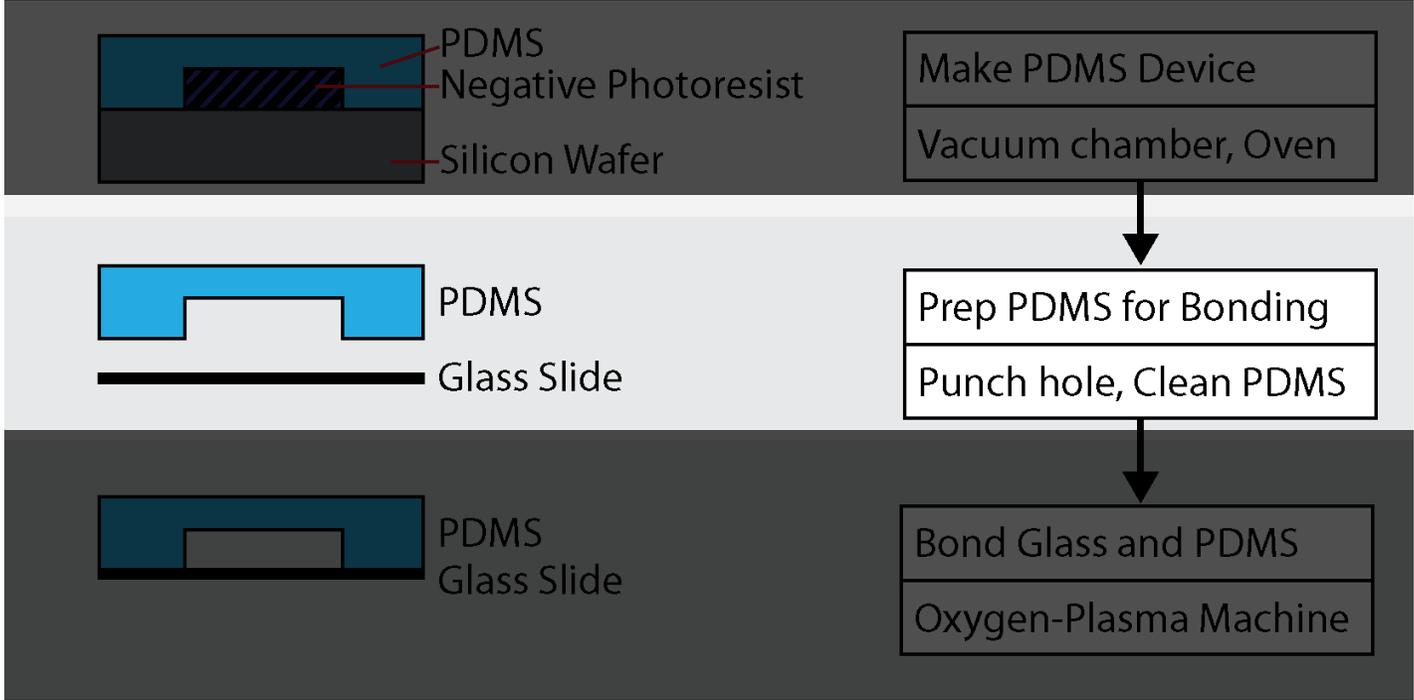
Part 2: Microfluidic Device Manufacturing



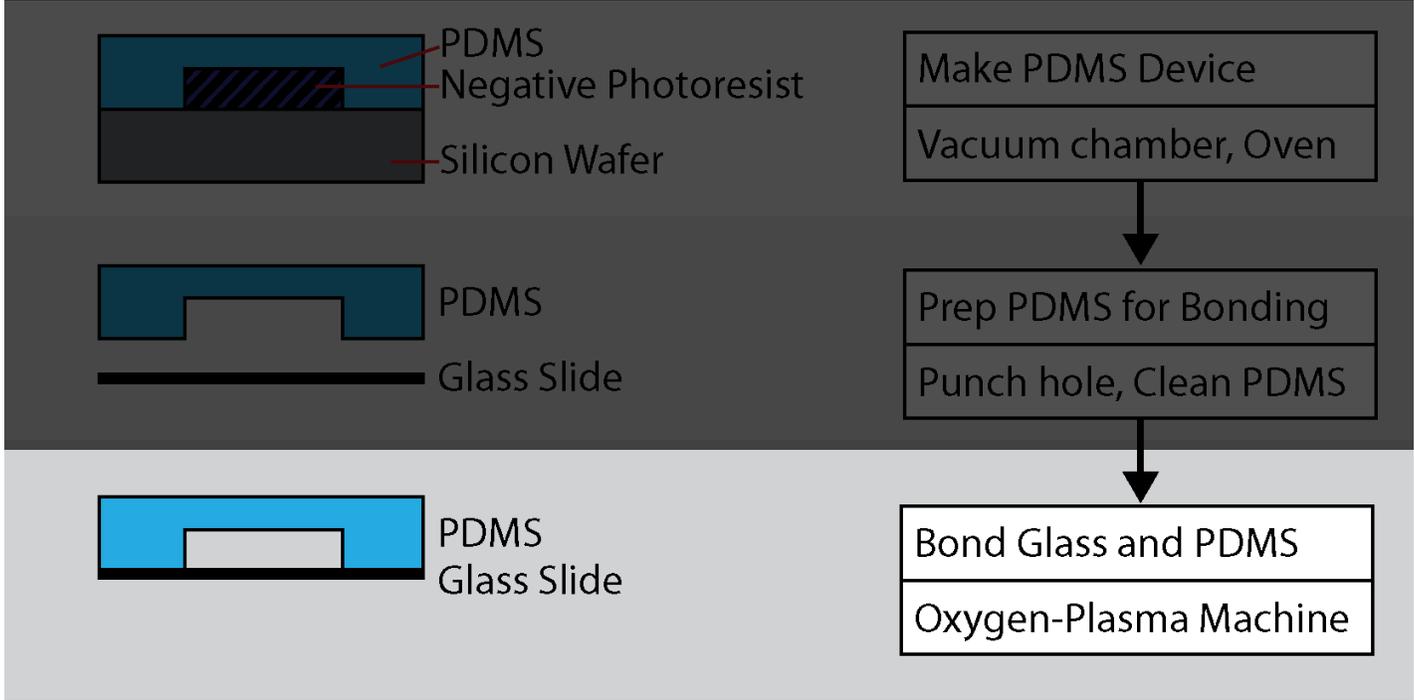
Part 2: Microfluidic Device Manufacturing

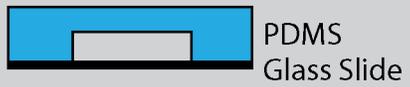
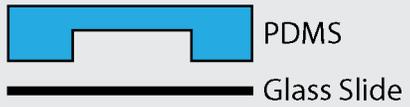
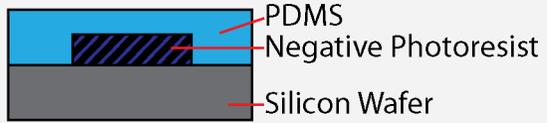


Part 2: Microfluidic Device Manufacturing



Part 2: Microfluidic Device Manufacturing





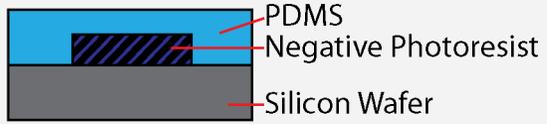
Make PDMS Device
Vacuum chamber, Oven



Prep PDMS for Bonding
Punch hole, Clean PDMS



Bond Glass and PDMS
Oxygen-Plasma Machine



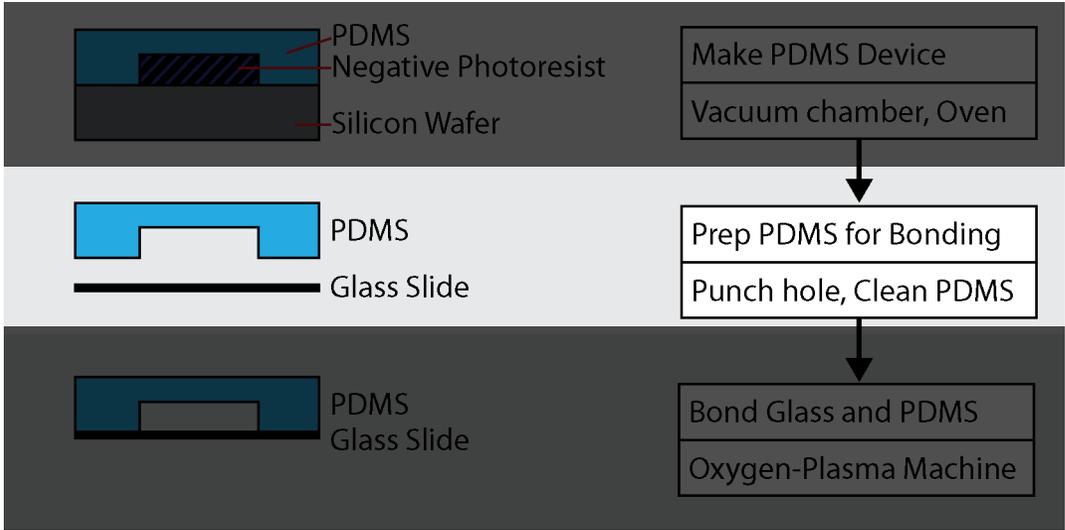
Make PDMS Device
Vacuum chamber, Oven

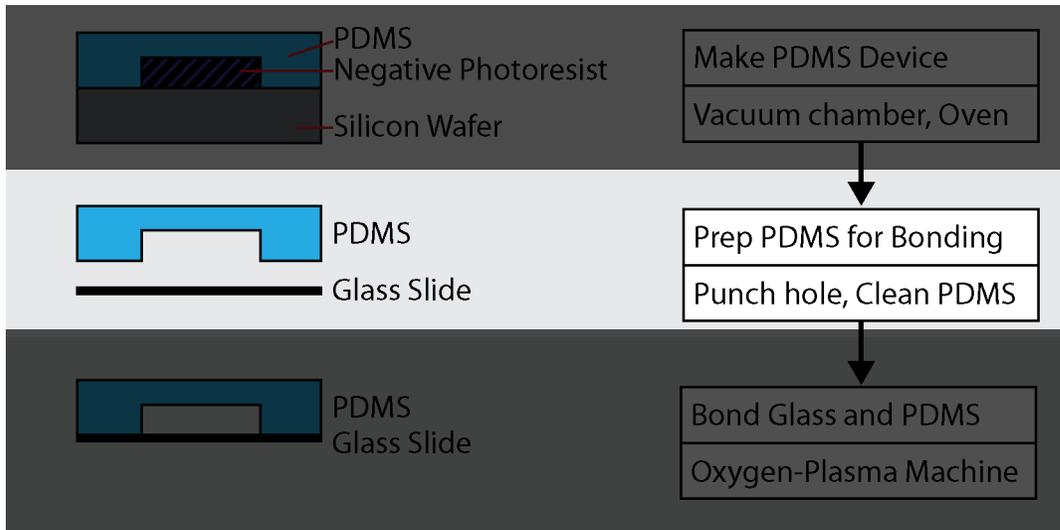


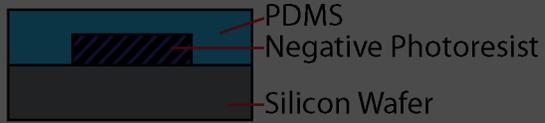
Prep PDMS for Bonding
Punch hole, Clean PDMS



Bond Glass and PDMS
Oxygen-Plasma Machine



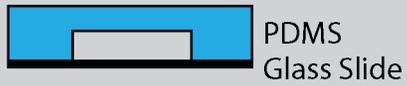




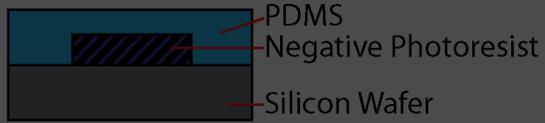
Make PDMS Device
Vacuum chamber, Oven



Prep PDMS for Bonding
Punch hole, Clean PDMS



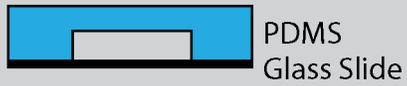
Bond Glass and PDMS
Oxygen-Plasma Machine



Make PDMS Device
Vacuum chamber, Oven



Prep PDMS for Bonding
Punch hole, Clean PDMS



Bond Glass and PDMS
Oxygen-Plasma Machine

